LTC6812 PCN Datasheet Changes

LTC6812-1

	MIN (OLD)	MIN (NEW)
t_{CYCLE}	1692	1455
	352	303
	2382	2049
	145.2	124.9
	29.1	25.0
	203.2	174.8
	811	697
	176	151
	1149	988
t_{SKEW1}	168	144
	470	404
t_{SKEW2}	162	139
	464	400
t_{SKEW3}	127	109
	354	304

SYMBOL	PARAMETER	CONDITIONS		MIN	TYP	MAX	UNITS
ADC Timing Specifications							
t_{CYCLE} (Figure 3, Figure 4, Figure 6)	Measurement + Calibration Cycle Time When Starting from the REFUP State in Normal Mode	Measure 15 Cells	●	1692	1956	2077	µs
		Measure 3 Cells	●	352	407	432	µs
		Measure 15 Cells and 2 GPIO Inputs	●	2382	2753	2924	µs
	Measurement + Calibration Cycle Time When Starting from the REFUP State in Filtered Mode	Measure 15 Cells	●	145.2	167.8	178.2	ms
		Measure 3 Cells	●	29.1	33.6	35.7	ms
		Measure 15 Cells and 2 GPIO Inputs	●	203.2	234.9	249.5	ms
	Measurement + Calibration Cycle Time When Starting from the REFUP State in Fast Mode	Measure 15 Cells	●	811	937	996	µs
		Measure 3 Cells	●	176	203	215	µs
		Measure 15 Cells and 2 GPIO Inputs	●	1149	1328	1410	µs
t_{SKEW1} (Figure 6)	Skew Time. The Time Difference Between GPIO2 and Cell 1 Measurements, Command = ADCVAX	Fast Mode	●	168	194	206	µs
		Normal Mode	●	470	543	577	µs
t_{SKEW2} (Figure 3)	Skew Time. The Time Difference Between Cell 15 and Cell 1 Measurements, Command = ADCV	Fast Mode	●	162	187	198	µs
		Normal Mode	●	464	536	569	µs
t_{SKEW3} (Figure 6)	Skew Time. The Time Difference Between Cell 15 and GPIO1 Measurements, Command = ADCVAX	Fast Mode	●	127	147	156	µs
		Normal Mode	●	354	409	434	µs

ANALOG DEVICES

AHEAD OF WHAT'S POSSIBLE™

RELIABILITY DATA
LTC6812 & LTC6813 PCN

7/12/2019

• Operating Life Test

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +125°C	NUMBER OF FAILURES
LQFP	154	1916	1916	25.87	0
	154			25.87	0

• Early Life Failure Rate Test

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +125°C	NUMBER OF FAILURES
LQFP	800	1916	1916	38.40	0
	800			38.40	0

1. Electro-Static Discharge (ESD) Test Results

1.1 Test Description

The HBM ESD testing was performed on a THERMOFISHER Mk.2
using the Human Body Module per JESD22-A114. This test is performed for classification
only. **Class 1A >±250V, Class 1B >±500V, Class 1C >±1000V, Class 2 >±2000V,
Class 3A >±4000V and Class 3B >±8000V. A copy of the circuit is shown below:**

1.2 Test Circuit & Condition
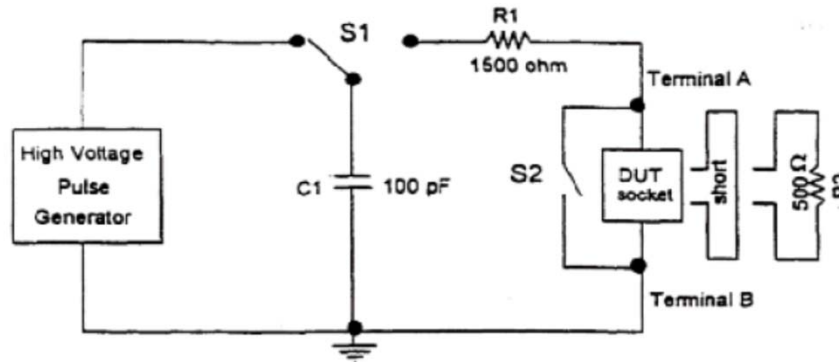
Figure 1 — Typical equivalent HBM ESD circuit

NOTE 1   The performance of any simulator is influenced by its parasitic capacitance and inductance.

NOTE 2   Precautions must be taken in tester design to avoid recharge transients and multiple pulses.

NOTE 3   R2, used for initial equipment qualification and requalification as specified in 3.1, shall be a low
inductance, 4000 V, 500 Ω resistor with +/-1% tolerance.

NOTE 4   Stacking of DUT socket adaptors (piggybacking) is allowed only if the waveforms can be verified to meet
the specifications in Table 1.

NOTE 5   Reversal of terminals A and B to achieve dual polarity is not permitted.

NOTE 6   S2 shall be closed at least 10 milliseconds after the pulse delivery period to ensure the DUT socket is not
left in a charged state.

NOTE 7   R1, 1500 Ω +/- 1%.

NOTE 8   C1, 100 pF +/- 10% (effective capacitance).

1.3 ESD Data

Device	Model	S/S	Pins	Voltage Passed	Voltage Failed
LTC6813	HBM Class 1C	3	All Pins	>±1000V	

1.7 Test Description

The Charged Device Model (CDM) ESD testing was performed on a THERMOFISHER RCDM system per ESDA ESD STM5.3.1-1999 / AEC-Q100-011-Rev-B. This test is performed for information only. A copy of the circuit is shown below:

1.8 Test Circuit & Condition
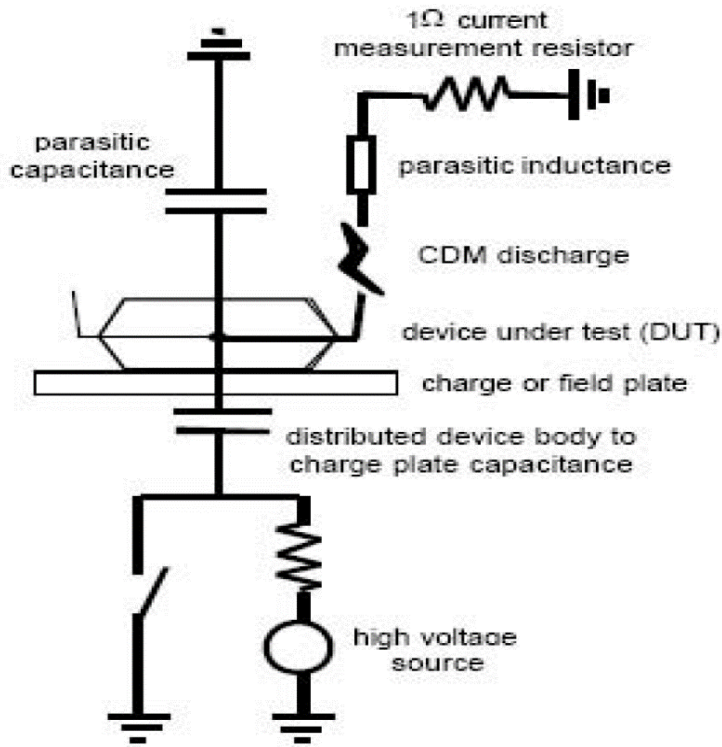
(b) Field induced charge CDM

1.9 ESD Data

Device	Model	S/S	Pins	Voltage Passed	Voltage Failed
LTC6813	CDM	3	All Pins	>±750V	

4. Latch-Up Test Results

4.1 Test Description

Latchup Testing was performed at +25°C and +125°C using the LTX Integrated Circuit Test system. The Power Supply pins are biased to the appropriate Datasheet specifications and the individual non-Power Supply pins are tested incrementally while the current is monitored until failure occurs.

4.2 Test Circuit & Condtion
4.2.1 Test Circuit 1
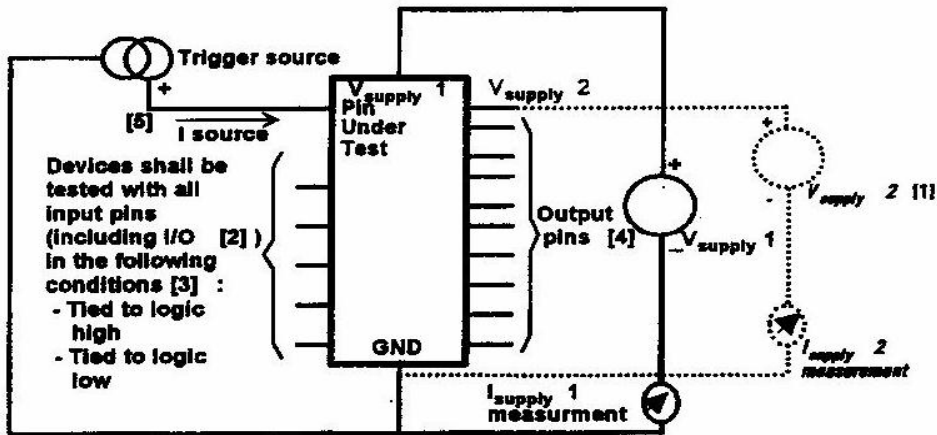
1. DUT biasing shall include additional V$_{supplies}$ as required.
2. DUT shall be preconditioned so that all I/O pins are placed in a valid state per 4.1. I/O pins in the output state shall be open circuit.
3. Logic high and logic low shall be per the device specification. When logic levels are used in respect to a non-digital device, it means the maximum high or minimum low voltage that can be supplied to the pin per the device specifications, unless these conditions violate device setup condition requirements.
4. Output pins shall be open circuit except when latch-up tested.
5. The trigger test condition is defined in figure 2 and table 1.

NOTE: Dynamic devices may have timing signals applied per 4.2.3.

Figure 5 - The equivalent circuit for positive input/output I-test latch-up testing

4.2.2 Test Circuit 2
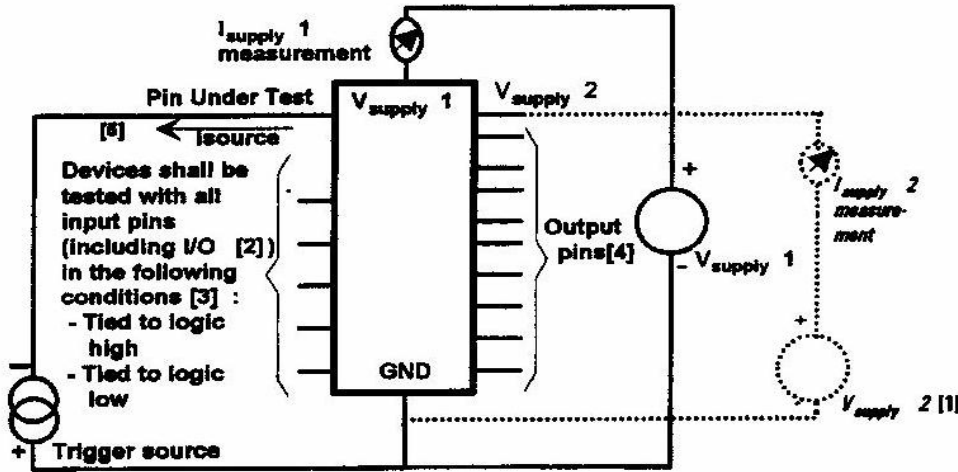
1. DUT biasing shall include additional Vsupplies as required.
2. DUT shall be preconditioned so that all I/O pins are placed in a valid state per 4.1. I/O pins in the output state shall be open circuit.
3. Logic high and logic low shall be per the device specification. When logic levels are used with respect to a non-digital device, it means the maximum high or minimum low voltage that can be supplied to the pin per the device specification, unless these conditions violate the device setup condition requirements.
4. Output pins shall be open circuit except when latch-up tested.
5. The trigger test condition is defined in figure 3 and table 1.

NOTE: Dynamic devices may have timing signals applied per 4.2.3.

Figure 6 - The equivalent circuit for negative input/output I-test latch-up testing

4.3 Latch-Up Data

Device	Mode	Current	Temp	S/S	Results
LTC6813	CKT1 & CKT2	>±200mA	+25°C	5	PASS
	CKT1 & CKT2	>±100mA	+125°C	5	PASS

DeltaQualifikationsMatrix

DeltaQualificationMatrix

Allgemeines

Kurze Produkt- und Technologiezyklen elektronischer Bauelemente sowie neue Umweltauflagen (Bleiverbot, Flammhemmer, …) führen häufig zu prozeß- und werkstofftechnischen Änderungen an Bauelementen, Leiterplatten, Verbindungstechnik und Schaltung, welche evaluiert werden müssen. Eine geeignete Methodik zur Handhabung von Änderungen an elektronischen Bauelementen beschreibt die ZVEI "Guideline for Customer Notifications of Product and /or Process Changes (PCN) of Electronic Components specified for Automotive Applications". Ein wesentlicher Teil dieser Guideline sind die hier vorliegenden Matrizen, welche sich als Empfehlungen für die Evaluierung von typischen Änderungen an elektronischen Bauelementen verstehen. Dies sollte Teil des offenen und risikobewussten Dialoges zwischen Lieferant und Kunden sein.

Diese DeltaQualifikationsMatrizen wurden durch den Industriearbeitskreis "PCN DeltaQualifikationsMatrix" und den Bauteilexperten des ZVEI Arbeitskreis "PCN-Methodik" erarbeitet. Der Inhalt wurde basierend auf dem aktuellen Stand der Technik erstellt und erhebt keinen Anspruch auf Vollständigkeit. Im Einzelfall ist ggf. ein abweichendes Vorgehen abzustimmen, da kundenspezifische Vereinbarungen zur Qualifikation zu berücksichtigen sind.

General

Short product and technology cycles as well as new environmental regulations („Pb-free", flame retardants, ….) frequently result in process and material changes of components, printed circuit boards, assembly techniques and circuit layout which have to be evaluated. The ZVEI "Guideline for Customer Notifications of Product and /or Process Changes (PCN) of Electronic Components specified for Automotive Applications" describes an appropriate methodology for dealing with changed electronic components. The qualification matrices in this guideline are recommendations for how to assess typical changes of electronic components. These recommendations promote an open risk-based discussion between supplier and customer regarding qualifications.

The DeltaQualificationMatrices were developed by the Industry Task Force Team "PCN DeltaQualificationMatrix" together with component experts from the ZVEI Working Group "PCN-Methodology". Actual content represents state-of-the-art technology and does not claim to be comprehensive. Deviation from proposed guideline should be mutually agreed as customer specific requirements have to be considered.

Anwendung der DeltaQualifikationsMatrix *(auszufüllen durch den Bauelementehersteller)*

a) Diese Tabelle ist **nur** bei Änderungen anzuwenden. Neuqualifikationen und Sonderqualifikation (z.B. Verguß von Modulen) sowie Information Notes bleiben von diesen Matrizen unberührt.

b) Ist eine Änderung in dieser Tabelle nicht aufgeführt, so ist der Qualifikationsumfang zwischen Kunde und Lieferant abzustimmen.

c) Die Matrix der Aktiven Bauelemente ist so aufgebaut, dass zwischen integrierten Halbleitern (AEC-Q100 Rev.H) und diskreten Halbleitern (AEC-Q101 Rev. D1) auszuwählen ist (Zelle D4). Für Passive Bauelemente gilt die AEC-Q200. Für LED's gilt die IEC 60810.

d) **Alle** Änderungen in der PCN sind in der Spalte B durch ein Kreuz (x) zu markieren und werden dadurch farblich hervorgehoben. Sofern dies geschehen ist, werden im Feld "*Tests, which should be considered for the appropriate process change*" (Zeile 83 für Aktive Bauelemente, Zeile 466 für Passive Bauelemente oder in Zeile 77 für LED's) alle in Betracht zu ziehenden Zuverlässigkeitstests angezeigt.

e) In "*Tests, which should be considered for the appropriate process change after selection of condition table*" (Zeile 85 für Aktive Bauelemente, Zeile 468 für Passive Bauelemente oder Zeile 79 für LED's) wird die Anpassung der in Betracht zu ziehenden Tests in Folge der Relevanz bezüglich der Änderung berücksichtigt.
Dazu ist die Tabelle "Conditions" entsprechend der Auswahl (A/B/C) mit einem (x) zu bewerten.

f) In "*Suppliers performed tests*" (Zeile 87 für Aktive Bauelemente, Zeile 470 für Passive Bauelemente oder Zeile 81 für LED's) dokumentiert der Bauelementehersteller die durchgeführten bzw. geplanten Tests.

g) Falls von der Testempfehlung abgewichen wird, so sollten diese Abweichungen vom Bauelementehersteller angezeigt und kommentiert werden. Hierzu ist der Bereich "*Reason for exception of tests*" (Zeile 89 für Aktive Bauelemente, Zeile 472 für Passive Bauelemente oder Zeile 83 für LED's) zu verwenden.
Werden die in Betracht zu ziehenden Tests durch generische Daten **(G)** belegt, ist dies ebenfalls hier anzuzeigen und zu begründen.

DeltaQualificationMatrix Application *(completion by component manufacturer)*

a) This table has to be used for changes **only.** The matrices are not applicable for new product, special qualifications (for instance for encapsulation of module) or Information Notes.

b) If a change is not listed in this table, the qualification plan has to be defined and agreed between customer and supplier.

c) The matrix for Active Components requires the user to chose between integrated circuits (AEC-Q100 Rev. H) and discret semiconductors (AEC-Q101 Rev.D1) (cell D4). For Passive Components AEC-Q200 is used. For LED'S the IEC 60810 is used.

d) **All** changes as listed in the PCN have to be marked by a cross (x) in column B and will appear colored. The relevant reliability tests are then shown in "*Tests, which should be considered for the appropriate process change*" (row 83 for Active Components, row 466 for Passive Components, respectively in row 77 for LED's).

e) In "*Tests, which should be considered for the appropriate process change after selection of condition table*" (see row 85 for Active Components, row 468 for Passive Components, or row 79 for LED's) is for modification of the found relevant tests under consideration of the weight of change. Related table "Conditions" has to be assessed per proposed letters with an (x).

f) In "*Suppliers performed tests*" (here row 87 for Active Components, row 470 for Passive Components, or row 81 for LED's) the component manufacturer documents the planned and performed tests.

g) In case of deviations from tests, which should be considered this should be notified and commented by the component manufacturer in the area "*Reason for exception of tests*" (see row 89 for Active Components, row 472 for Passive Components, or row 83 for LED's). Test results in form of generic data **(G)** are allowed when notified and justified.

Die Einstufung des Untersuchungslevel erfolgt in folgende Kategorien

"*C: Component level*": Die Evaluierung der Änderung am Bauelement ist durch Untersuchungen **ausschließlich** am Bauelelement beim Bauelementehersteller durchführbar. Zur Evaluierung der Änderung dürfen Ergebnisse aus bereits durchgeführten Untersuchungen herangezogen werden, wenn diese zu einem ähnlichen Bauelement bereits vorliegen **(Generische Daten)**.

"*B: Board level*": Die beschriebene Änderung hat möglicherweise Einfluss auf die Verarbeitbarkeit des Bauelementes im Steuergerät. Die Evaluierung der Änderung wird wie unter C beim Bauelementehersteller durchgeführt. Zusätzlich ist durch den Kunden/Steuergerätehersteller die Verarbeitbarkeit zu prüfen, die z.B. abhängig von der Änderung, Zuverlässigkeitsuntersuchungen auf applikationsrelevanten Testbords erfordert.

"*A: Application level*": Die beschriebene Änderung hat möglicherweise Einfluss auf die Applikation/ das Steuergerät. Die Evaluierung der Änderung wird wie unter C oder B durchgeführt. Zusätzlich ist vom Kunden/Steuergerätehersteller der Einfluss der Änderung im Steuergerät durch geeignete Untersuchungen zu bewerten. Dieses Vorgehen ist mit dem OEM abzustimmen. Hierbei ist zu berücksichtigen, ob die Steuergeräte- / Baugruppenanforderungen durch andere Qualifikationen bereits hinreichend abgesichert sind **(applikationsspezifische Risikobetrachtung)**.

" ***: Not relevant for qualification matrix**": Änderung(en), die nicht in A, B oder C eingestuft werden können und somit nicht relevant für die DeQuMA sind.

Evaluation Levels are categorized as follows

"*C: Component level*": The evaluation of a change at component level by the component manufacturer is sufficient. Generic data from other relevant evaluations can be used.

"*B: Board level*": The intended change described in the PCN may influence processability / manufacturability of the component at board level. Therefore additional evaluation by customer may be necessary, for example reliability tests on application relevant testboards, depending on change.

"*A: Application level*": The intended change described in the PCN may influence the properties of the application (e.g. Electronic Control Unit).
In addition to the evaluation under C or B the influence of the change in the application is evaluated by suitable investigations by the customer. The scope of the evaluation has to be aligned with the OEM. It has to be considered whether the application / assembly requirements are already sufficiently safeguarded by other qualifications **(application specific risk assessment)**.

" ***: Not relevant for qualification matrix":** Changes which fulfill neither A,B nor C definitions

Infomation Notes

Änderungen die nur eine Infomation Note benötigen (bei der Bewertung Risk on Supply Chain als "I" gekennzeichnet), dürfen nicht in der DeQuMa angekreuzt werden, da Sie ansonsten den erforderlichen Evaluierungslevel verfälschen. Für als "I" bewertete Änderungen ist das Information Note Formblatt zu verwenden.

Infomation Notes

Changes indicated as "I" shall not be marked in the DeQuMa. For those changes the InformationNote sheet shall be used. As the DeQuMa is desired for PCN only, a marking of "I"-changes would automatically influence evaluation level and test effort.

Wichtige Hinweise

- Zur formgerechten Anwendung der DeltaQualifikationsMatrizen steht auf der Homepage des ZVEI AK ein Tutorial bereit (ZVEI-Tutorial).
- ID Nummer: ist eine eindeutige Identifikationsnummer für jede angegebene Änderung, die in den ZVEI PCN DeltaQualifikatiosMatrizen identifiziert ist. Die gleiche ID Nummer wird zur Identifizierung der Änderung im PCN Form Sheet verwendet.
- Die mittels Matrix identifizierten Tests sind in **Betracht zu ziehen**, d.h. es ist zu prüfen, ob der jeweilige Test für die spezifische Änderung in dieser Form notwendig ist. Abweichungen oder generische Daten sind im Detail zu begründen.
- Die Spalte "Further applicable conditions", Bemerkungen und Fußnoten sind unbedingt zu beachten, da sie wichtige Hinweise und Einschränkungen enthalten.
- Zur Nutzung aller Funktionen muss in Excel die Anwendung von Makros freigegeben sein.

Important Notes

- To use the matrices in the right form the ZVEI working group provides a Tutorial on its homepage (ZVEI-Tutorial)
- ID number: is a unique identification number for each indicated change defined in the ZVEI PCN DeltaQualificationMatrices. The same ID number is used in the PCN Form sheet to identify the change.
- Tests identified by the matrix have **to be considered** and checked if they are necessary to assess the specific change. Test modifications or generic data have to be justified in detail.
- "Further applicable conditions", comments and notes need attention, as they provide important hints and limitations.
- In order to use all functions in EXCEL, macros have to be allowed.

History of DeQuMa

Version	Remarks
2.0	Revised by ZVEI PCN Methodology Workgroup in March 2015
2.1	Released March 2015
2.1.1	Active Components - delete write protection in comments
2.2	Solved problems with some ActiveX configurations
2.2.2	Solved Problems in Active Components
2.2.3	Solved Problems ActiveX, Active Components SEM-DE-02 (Design changes in routing) error fixed
2.2.4	Minor fixes
3.0	General Revision by ZVEI PCN Methodology Workgroup in June 2016 Changes are indicated by underlining in the read only version named Changes_DeQuMa_rev3_vs_rev2.xlsx
3.0.4	Expert Release
3.0.5	Fixing of macro bugs
3.1	Final Release (orthographic and punctuation corrections)

Worked on: (Name, Function)	Sabine Koschack
Date:	18/07/2019
PCN number:	19_0141
Signature:	
For integrated circuits or discrete semiconductors select below:	AEC-Q100 Revision H

Form provided by ZVEI – Revision 3.1 – December 2016

Mark change with an "x"

MATERIAL PERFORMANCE TEST RESULTS (on the basis of AEC-Q100 Revision H)
includes integrated circuits (e.g. ASICs, µ-Controler, memories, voltage regulators, smart power devices, logic devices, analog devices,...)

additional to AEC-Q10x

ID	Type of change	No	Yes	Understanding of semiconductors experts	Examples to explain	Evaluation level A / B / C	Further applicable conditions	AEC-Q100 Revision H	Remarks
ANY									
SEM-AN-01	Any change with impact on agreed upon contractual agreements	P	P	Not relevant for technical evaluation.		*			
SEM-AN-02	Any change which is not covered in the matrix below, but risk assessment at customer is recommended.	P	P	Any change which is not covered in the matrix below, but risk assessment at customer is recommended.		B			
DATA SHEET									
SEM-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	P	P	Update of data sheet because of technical change of the product.	e.g. recommendations for pull-up/pull-down or NC pins, MSL.	A			
SEM-DS-02	Correction of data sheet / errata	I	P	No technical change of the product, only correction in description (wording, drawing, ...). (I): In case of editorial changes. (P): In case of impact on product integrity.	(I): e.g. correction of typo (P): e.g. datasheet correction because of new information about component behavior.	A			
SEM-DS-03	Specification of additional parameters	I		Description of a new not previously covered parameter. No technical change of the product. (I): Definition of new parameter which was not documented before. (P): Not known as single change. Only in combination with other changes.	(I): e.g. adding new tested parameter.	A			
DESIGN									
SEM-DE-01	Design changes in active elements. [1]	P	P	Any device relevant changes in design / layout of elements with effect on data sheet [1] **Not included:** Modification to adjust product parameter within specified process window and design rules.	e.g. change of ESD structure e.g. add / remove a transistor in layout	A	Please check if data sheet is affected (SEM-DS-01).		
SEM-DE-02	Design changes in routing . [2]	P	P	Any change of wiring between elements in chip design / layout with effect on data sheet. [2] **Not included:** Modification to adjust product parameter within specified design rules.	e.g. mask changes in metal fix for corrective action (based on external 8D report)	C	A: Impact on EMC behavior cannot be evaluated / excluded on component level. A: If impact on electrical function is not excluded on component level. Please check if data sheet is affected (SEM-DS-01).		
SEM-DE-03	Die shrink [3]	P	P	Shrink of active area. [3] **Not included:** sawing street/kerf/scribe line	Typical shrink of die.	A	Please check if change in process technology (SEM-PW-09) is also affected. In case of Cu wire product please consider AEC-Q006.		
SEM-DE-04	Firmware modification	I	P	Integrated software by design or memory as defined by supplier. (I): Firmware modification or update without effect of functional performance at the customer (bug fix). (P): Firmware modification or update with effect of functional performance at the customer.	(I): e.g. addition of Firmware opportunities (P): e.g. bug fix with impact on functional performance.	A			
PROCESS - WAFER PRODUCTION									
SEM-PW-01	New / change of wafer substrate material	P	P	New wafer material.	e.g. different wafer material to currently released material (like change from EPI material into non-EPI material)	C	In case of Cu wire product please consider AEC-Q006.		Qualification effort acc. AEC-Q100: see diffusion/doping
SEM-PW-02	New wafer diameter	P	P	Change of wafer diameter resulting in equipment and process changes.		C	Impact on changes in SEM-PW-09 and/or SEM-EG-01.		AEC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, processes), refer to section A1.3 of this appendix and section 2.3 of Q100, which allows for the selection of worst-case test vehicles to cover all the possible permutations."
SEM-PW-03	New final wafer thickness	P	P	Change in final wafer thickness.	e.g. change in final chip/die thickness	C	A: If thermal conductivity is affected (like MOSFET, IGBT, BGA package, stacked dies, ...) A: If impact on EMC or ESD behavior cannot be evaluated / excluded on component level. In case of Cu wire product please consider AEC-Q006.		
SEM-PW-04	Change of electrically active doping/implantation element	P	P	Change in electrically active doping / implantation element resulting in a new technology.		A			
SEM-PW-05	Change of gate material / dielectrics	P	P	Change of gate material and / or gate dielectric.		A			
SEM-PW-06	New / change of backside operation (grinding / metallization)	P	P	Change of bottom layer of die (between die and leadframe). Change in process, material, or dimensions necessary. Alternative see SEM-PW-09	e.g. change from Cr/Ni/VAu to Cr/Ni/VAg	C	A: If thermal conductivity is affected (like MOSFET, IGBT, BGA package, stacked dies, ...) A: If impact on EMC or ESD behavior cannot be evaluated / excluded on component level.		AEQ-Q100: Applicable to all smart power devices
SEM-PW-07	New / change of metallization / vias / contacts	P	P	Change in metallization of bondpads, material, layer thickness specifically for chip frontside and internal layers.	e.g. change from AlSiCu to AlCu e.g. change in over pad metallization	C	In case of Cu wire product please consider AEC-Q006.		
SEM-PW-08	New / change of passivation or die coating (without bare die)	P	P	Change of top layer on die (between mold compound and die).	e.g. addition of polyimide	C	Change of intrinsic mechanical stress might influence electrical function. In case of Cu wire product please consider AEC-Q006.		
SEM-PW-09	Change in process technology. (e. g. process changes like lithography, etch, oxide deposition, diffusion, die back surface preparation/backgrind, ...)	--	P	(--): If the change in process technology does not influence the integrity of the final product. (P): If the change in process technology can influence the integrity of the final product.	(--): e.g. change from wet to dry etching. e.g. change from horizontal to vertical oven for oxidation (P): e.g. change of layer thickness	A	Please also check changes described under EQUIPMENT. Please check if change is described by specific type of change in this matrix.		Qualification effort depends on type of change.
SEM-PW-10	Process integrity: tuning within specification	--	P	Variation within process specification. (--): If tuning within process specification does not influence the integrity of the final product. (P): If remaining risk on product specification is anticipated.	(--): e.g. process control	C	Please check if DATA SHEET is affected. Please check if SEM-PW-09 is affected.		
SEM-PW-11	Change of wafer supplier.	--	P	(--): If no remaining risk in supply chain exist (P): If the change of wafer supplier can influence the integrity of the final product.	(--): e.g. change of wafer supplier with same material composition. e.g. same material composition and does not influence electrical behavior. (P): e.g. new supplier with impact on substrate material and / or electrical behavior.		Not on component, tested on test structure (typical for IC). Interaction on component level for discrete components expected. In case of SOI substrate HF properties have to be qualified. Please check if SEM-PW-01 and SEM-DS-01 is affected.		Qualification for IC & µ-Controller difficult on product level. Characterisation on wafer level only on test structure. AEC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, processes), refer to section A1.3 of this appendix and section 2.3 of Q100, which allows for the selection of worst-case test vehicles to cover all the possible permutations."
SEM-PW-12	Change of specified wafer process sequence (deletion and/or additional process step)	--	P	Any change which is not covered by another type of change. Risk is to be assessed. (--): No Risk for Supply chain. (P): Risk for Supply chain (influence on product integrity)	(--): e.g. change of cleaning process in wafer production (P): e.g. additional sinker implantation after standard implantation (to protect circuit against interference impulses).	C			
SEM-PW-13	Move of all or part of wafer fab to a different location/site/subcontractor	P	P	Wafer fab transition with additional changes (described above).	e.g. dual source / fab strategy	A	In case of Cu wire product please consider AEC-Q006.		AEC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, processes), refer to section A1.3 of this appendix and section 2.3 of Q100, which allows for the selection of worst-case test vehicles to cover all the possible permutations."
SEM-PW-14	Lithography	--	P	Change in process technique for lithographic process and material (--): If the change in process technology does not influence the integrity of the final product. (P): If the change in process technology can influence the integrity of the final product.	(--): e.g. exchange of defect mask (P): e.g. change from E-beam process to X-ray process e.g. change from contact into projection mode	C	Please also check changes described under EQUIPMENT.		

ID	Category / Title	Col1	Col2	Description	Examples	Class	Notes
SEM-PW-15	Oxide / Interlayer Dielectric	–	P	Change in process technique for oxide / interlayer dielectric process. (–): If the change in process technology does not influence the integrity of the final product. (P): If the change in process technology can influence the integrity of the final product.		A	Please also check changes described under EQUIPMENT.
	BARE DIE						
SEM-BD-01	New final wafer thickness	P	P	Change in final wafer thickness	Change in final chip/die thickness	A	In case of Cu wire product please consider AEC-Q006.
SEM-BD-02	New / change of frontside metallization	P	P	Change in bondpads, material, pad pitch, surface changes, layer thickness.	e.g. change from AlSiCu to AlCu e.g. change in over pad metallization	B	In case of Cu wire product please consider AEC-Q006.
SEM-BD-03	New / change of backside metallization	P	P	Change of bottom layer of die (between the die and leadframe). Change in process, material, or dimensions.	e.g. change from Cr/Ni/VAu to Cr/Ni/VAg	A	
SEM-BD-04	Change of wafer setup or number of possible good dies on wafer.	I	P	Needed information for pick & place machine. (I): amount of possible good dies on wafer (P): influence on wafer setup and wafer mapping.	(I): e.g. change from 350 to 240 good dies on wafer. (P): e.g. information change for pick & place machine.	B	
SEM-BD-05	Change of optical appearance of wafer edge region (like imide coverage or edge exclusion)	I	P	Selection of dies in wafer edge region which have full electrical functionality. (I): in case of wafer edge is affected only (P): in case of single die is affected	(I): e.g. appearance of wafer edge (rounded instead of square) (P): e.g. polyimide as new coating on die	B	
SEM-BD-06	Die scribe or separation	I	P	Needed information for sawing and pick & place machine. (I): If the change in sawing process does not influence the integrity of the final product. (P): in case if product is delivered on wafer	(I): e.g. if product is delivered as known good die (in tape and reel) (P): e.g. information change for pick & place machine. e.g. information change for sawing machine.	B	Please check if SEM-BD-04 is affected.
SEM-BD-07	Die Preparation / Clean	–	P	Change in process technique for die preparation / cleaning (–): If the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. change of cleaning time. (P): e.g. change in cleaning procedure after change of sawing equipment.	B	Please check if SEM-BD-06 is affected.
SEM-BD-08	New / change of passivation or die coating	P	P	Change of top layer on die.	e.g. addition of polyimide e.g. change of polyimide thickness	B	In case of Cu wire product please consider AEC-Q006.
	PROCESS - ASSEMBLY						
SEM-PA-01	Change in critical dimensions of package	P	P	Change in dimensions of existing package.	e.g. changes in package dimensions (further development).	B	
SEM-PA-02	Change of leadframe base material	P	P	New leadframe material in new composition.	e.g. change from alloy42 to copper e.g. change between two different copper alloys	B	In case of Cu wire product please consider AEC-Q006.
SEM-PA-03	Change in leadframe dimensions	P	P	Change in leadframe dimensions which has impact to the specified electrical parameter acc. data sheet or specification (e.g. heat sink, pin dimensions, die paddle size, ...) Not included: Variation within specification.	e.g. change in lead frame geometry	B	ESD investigations are only necessary if internal ground and power supply connection of leadframe is affected. A: If impact on EMC behavior cannot be evaluated / excluded on component level. In case of Cu wire product please consider AEC-Q006.
SEM-PA-04	Change of lead frame finishing material / area (internal)	P	P	Change of surface material of die attach pad and second bond area (e.g. influence in adhesion to mold compound, wedge bond reliability)	e.g. change from Ag flash to NiP protection layer e.g. change from Ag spot to Au spot e.g. increase of silver plating area	C	In case of Cu wire product please consider AEC-Q006.	For wire bond strength test: Pre- & Post-process change comparison to evaluate process change robustness (AEC-Q101).
SEM-PA-05	Change of lead and heat slug plating material/plating thickness (external)	P	P	Change in material and / or process resulting in a new technology (e.g. pure tin).	e.g. change in heat slug stack e.g. change from Sn into NiPdAu e.g. change of layer thickness	B	
SEM-PA-06	Bump Material / Metal System (internal)	P	P	Stack die or die to substrate (flip chip)	e.g. change to Pb-free material e.g. change of copper pillars	C	
SEM-PA-07	Die attach material	P	P	Change of die attach material and / or process resulting in a new technology (e.g. soft solder, epoxy, etc.)		C	A: If impact on EMC behavior cannot be evaluated / excluded on component level (if die attach has impact on electrical conductivity). In case of Cu wire product please consider AEC-Q006.
SEM-PA-08	Change of wire bonding	P	P	Material, diameter, change in bonding diagram and / or change in process resulting in a new technology.	e.g. change from Au to Cu material e.g. change from 25µm to 23µm diameter e.g. change from single to double bond e.g. change from stich bond to stich on ball bond.	C	A: In case of bond diagram change and EMC cannot be evaluated on component level. Please also check changes described under SEM-EQ-01. In case of Cu wire bonding please consider AEC-Q006.	Parameter Analysis: Strictly required only for Power devices. In general: Site audit for material change with impact on bondprocess (e.g. from Au to Cu) recommended. AEC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, processes), refer to section A1.3 of this appendix and section 2.3 of Q100, which allows for the selection of worst-case test vehicles to cover all the possible permutations."
SEM-PA-09	Substrate / Interposer	P	P	Change of BGA substrate	e.g. changes in routing	B	A: Impact on EMC behavior cannot be evaluated / excluded on component level. A: If impact on electrical function is not excluded on component level. In case of Cu wire product please consider AEC-Q006.
SEM-PA-10	Die Overcoat / Underfill	–	P	Supporting layers for complex packages like flip chip and / or change in process resulting in a new technology. (–): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. change of dispensing speed (P): e.g. change of underfill material	C	
SEM-PA-11	Change of mold compound / encapsulation material	P	P	Change of mold compound / encapsulation material.	e.g. change to green mold compound e.g. change of filler particles	B	A: impact on thermo-mechanical stress caused by mismatch of mold compound, interconnecting technology and carrier is evident anticipated (specific for Power Devices). A: In case of high frequency signals (> 3GHz) it should be assessed if possible changes in permeability of mold compound could affect signal behavior (e.g. digital signal processor). In case of Cu wire product please consider AEC-Q006.
SEM-PA-12	Change of hermetic sealing	P	P	Affected areas are material and process of hermetic (e.g. ceramic-) packages, capped die and sealed devices (e.g. pressure sensors)	e.g. change of sealing material for RoHS	B	A: Impact on EMC behavior cannot be evaluated / excluded on component level (if encapsulation / sealing has impact on electrical conductivity).
SEM-PA-13	Change of product marking	I	P	Change of marking on device and / or change in process resulting in a new technology. (I): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(I): e.g. change of appearance (additional marking) (P): e.g. change from inked marking to laser marking e.g. marking of pin 1	B	
SEM-PA-14	Change in process technology (e.g. sawing, die attach, bonding, molding, plating, trim and form, lead frame preparation, ...)	–	P	(–): If the change in process technology does not influence the integrity of the final product. (P): If the change in process technology can influence the integrity of the final product.	(P): e.g. change from ball bond to stitch	B	Please also check changes described under SEM-EQ-01. Please check if change is described by specific type of change in this matrix.
SEM-PA-15	Process integrity: tuning within specification	–	P	Variation within process specification (–): If tuning within process specification does not influence the integrity of the final product. (P): If impact on product specification is anticipated.	(–): e.g. process control	C	
SEM-PA-16	Change of direct material supplier	–	P	Change of suppliers for direct materials which are used in assembly process (BOM). (–): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. change of wire material supplier. (P): e.g. change to new mold compound supplier e.g. additional leadframe supplier with specific leadframe manufacturing technology	C	Please check if material is changed!	See change of material.
SEM-PA-17	Change of specified assembly process sequence (deletion and/or additional process step)	–	P	(–): no influence in final product integrity or specified sequence (P): influence in final product integrity or specified sequence	(–): e.g. additional cleaning step e.g. deletion of optical inspection (P): e.g. change lead finishing pre trim & form to post trim & form	C		Qualification depends on specific change.
SEM-PA-18	Move of all or part of assembly to a different location/site/subcontractor.	P	P	Assembly transfer or relocation	e.g. dual source / fab strategy	C	A or B: Impact on other type of changes described under PROCESS ASSEMBLY and SEM-EQ-01. In case of Cu wire product please consider AEC-Q006.	Whisker tests have to be done on monitoring basis! AEC-Q100: "For broad changes that involve multiple attributes (e.g., site, materials, processes), refer to section A1.3 of this appendix and section 2.3 of Q100, which allows for the selection of worst-case test vehicles to cover all the possible permutations."
SEM-PA-19	Die scribe or separation	–	P	Separation process from single wafer to dies. (–): If the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. change of kerf width (P): e.g. change from sawing to laser cut	C	
SEM-PA-20	Die Preparation / Clean	–	P	Change in process technique for die preparation / cleaning (–): If the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. change of cleaning time.	C	
SEM-PA-21	Molding / Encapsulation process	–	P	Change in process technique for molding / encapsulation. (–): If the change in process does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. tuning within process specification	C	
	PACKING/SHIPPING						

ID			Description				
SEM-PS-01	Packing/shipping specification change	P	P	Packing/shipping specification change.		*	
SEM-PS-02	Dry pack requirements change	P	P	Change of dry pack requirements (e.g. change of MSL)		*	
SEM-PS-03	Change of carrier (tray, reel)	P	P	Change of carrier (tray, reel)		B	
SEM-PS-04	Change of labelling	I	P	Change of labelling also on reel. (I): Change of material label without impact on barcode. (P): Changes of material label information which affects data processing at customer.	(I) e.g. additional information (RoHS stamp) (P) e.g. change of defined nomenclature for data processing	B	
	EQUIPMENT						
SEM-EQ-01	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above.	Change from single wafer to batch process (e.g. over pad metalisation) e.g. dambar cutting (mechanical to laser cutting)	A	Affected process change is to check.
SEM-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	–	P	PCN required for dedicated equipment for sensitive component production. (–): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. extension of existing equipment pool (P): e.g. extension of dedicated equipment in case basic technology still need to be proven	C	
SEM-EQ-03	Change in final test equipment type that uses a different technology.	P	P	Change of tester (only in case of bare die: final test means wafer test.)	e.g. change tester equipment from LTX to Teradyne	C	Gage R&R / delta correlation
	TEST FLOW						
SEM-TF-01	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	P	P	Tester transfer or relocation. Check impact on SEM-AN-01	Dual source strategy	C	Gage R&R / delta correlation
	Q-GATE						
SEM-QG-01	Change of the test coverage/testing process flow used by the supplier to ensure data sheet compliance (e.g. elimination/addition of electrical measurement/test flow block; relaxation/enhancement of monitoring procedure or sampling)	–	P	e.g. test flow block, reduction from three temperature measurements to two temperature measurements, change in burn in / run in process. (–): If change does not influence the integrity of the final product. (P): If impact on product integrity is anticipated.	(–): e.g. test implemented without customer requirement (P): e.g. reduction from three temperature measurements to two temperature measurements e.g. change in burn in / run in process	C	Parameter Analysis: Delta correlation " For "burn in" changes ELFR recommended

Tests, which should be considered for the appropriate process change.	A	-	•	-	-	-	A	M	•	...
Tests, which should be considered for the appropriate process change after selection of condition table.		-	•	-	-	-		M	•	...
Suppliers performed tests (mark with an 'X' for done or 'G' for generic)		-	1	2	X	X	-	...

Reason for exception of tests and/or usage of generic data:
1 - Not a peripheral routing change
2 - part does not dissipate >1W
3 - performed only if mutually agreed on a case by case basis
4 - This is not a Smart Power device

–	Not required.
i	Information Note required.
P	PCN required.

A letter or "•" indicates that performance of that stress test should be considered for the appropriate process change.

	CONDITIONS	
A	Only for peripheral routing	X
B	For symbol rework, new cure time, temp	X
C	If bond to leadfinger	X
D	Design rule change	X
E	Thickness only	X
F	MEMS element only	X
G	Generic Data available	
H	Hermetic only	X
J	EPROM or EEPROM	
L	Lead free	
M	For devices requiring PTC	
N	Passivation and gate oxide	X
P	Passivation and interlevel dielectric	X
Q	Wire diameter decrease	X
T	Only for Solder Ball SMD	X
#	Only from non-100% burned-in parts	X
*	For "burn in" changes IOL or ELFR recommended	X

=> Please mark 'NO' with 'X', default is 'YES'

A letter or "•" indicates that performance of that stress test should be considered for the appropriate process change.

Worked on: (Name, Function)	Max Mustermann
Date:	
PCN number:	
Signature:	

Device evaluation

additional to AEC-Q200 Revision D — additional to AEC-Q200

Mark change with an "x"

Selection of component	ID	Type of change	Remaining risks on Supply Chain? No / Yes	Understanding of component experts	Examples to explain	Evaluation level A / B / C	Further applicable conditions	Use evaluation (can be evaluated by data or auditing site check)	AEC-Q200 Revision D	Checked specification (for one material only)	Remarks

NETWORKS & RESISTORS

ANY

| | PAS-RES-AN-01 | Any change with impact on special customer characteristics/contractual agreements | P / P | | | * | Not relevant for technical evaluation. | | | | |
| | PAS-RES-AN-02 | Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below. | P / P | | | B | Technical interface means component terminals. | | | | |

DATASHEET

	PAS-RES-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P / P	Change of application relevant information **Not included:** Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.				
	PAS-RES-DS-02	Correction of data sheet	I / P	No technical change of the product, only correction in description (wording, drawing, ...) **(I):** In case of editorial changes. **(P):** In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A					
	PAS-RES-DS-03	Specification of additional parameters	I / P	Description of a new not previously covered parameter. No technical change of the product. **(I):** no influence **(P):** Risk assessment depending on change for each application to provide evidence of additional parameter (stat. evaluation)	e.g. adding new (tested) parameter.	A					

MATERIAL

	PAS-RES-MA-01	Change of material composition - Ink/Wire material of Resistor element	P / P	Change of Ink / Wire material	e.g. resistor paste, NiCr, resistor wire	C					
	PAS-RES-MA-02	Change of material composition - Ink/Wire material of Terminal element	P / P	Change of Ink / Wire material	e.g. AgPd paste, Ag paste, lead wire , NiCr for side termination	B					
	PAS-RES-MA-03	Change of material composition - Package/ Mold	P / P	Change of Package	e.g. for chip res.: final coating, epoxy	C					Check whether AOI striker 1 can be affected.
	PAS-RES-MA-04	Change of material composition - Passivation	P / P	Change of Passivation /inner protection	e.g. change of glass	C					
	PAS-RES-MA-05	Change of material composition - Substrate material	P / P	Change of substrate material		C					
	PAS-RES-MA-06	Change of supplier of material	- / P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C					Assumption material specification remains unchanged. Otherwise see change of material.

DESIGN

| | PAS-RES-DE-01 | Changes of termination, surface finish, shape, color, appearance or dimension structure | I / P | Change of package | | B | | | | | |
| | PAS-RES-DE-02 | Change of inner construction - Passivation | - / P | Change of passivation/inner protection | e.g. change of glass, laquer, epoxy, ... | C | | | | | |

PROCESS

	PAS-RES-PR-01	Changes in process technology or manufacturing methods - Ink Fire	- / P	Change of ink fire process	e.g. change of firing profile e.g. change from normal atmosphere to nitrogen atmospher	C					
	PAS-RES-PR-02	Changes in process technology or manufacturing methods - Ink Print	- / P	Change of ink print process		C					
	PAS-RES-PR-03	Changes in process technology or manufacturing methods - Trim	- / P	Change of trim process	e.g. change from mill trimming to laser trimming	C					
	PAS-RES-PR-04	Changes in process technology or manufacturing methods - Lead Form	- / P	Change of lead form process	e.g. change from bending to punching	B					
	PAS-RES-PR-05	Changes in process technology or manufacturing methods - Termination Attach	- / P	Change of termination attach process	e.g. chip resistors: electroplating process e.g. welding of leads for through put devices.	B					
	PAS-RES-PR-06	Changes in process technology or manufacturing methods - Marking	- / P	Change of marking process	e.g. change from tampon printing to laser marking	B					
	PAS-RES-PR-07	Changes in process technology or manufacturing methods - Molding	- / P	Change of molding process		B					
	PAS-RES-PR-08	Process integrity: tuning within specification	- / P	Variation within process specification.	e.g. process control	C					

PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS

	PAS-RES-PN-01	Packing / shipping specification change (loosening of tolerances)	P / P	Change of packing specification.	e.g. number of pieces on reel.	B					
	PAS-RES-PN-02	Dry pack requirements change	P / P	Change of dry pack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B					
	PAS-RES-PN-03	Change of carrier (tray, reel)	P / P	Change of carrier	e.g. change by material e.g. change by geometry.	B					

PACKING / SHIPPING - VISUAL INSPECTION

	PAS-RES-PV-01	Change of labelling	I / P	Change of labelling, also on reel.	**(I)** e.g. additional information (RoHS stamp) **(P)** e.g. change of customer specific information	B					
	PAS-RES-PV-02	Change of product marking	I / P	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B					
	PAS-RES-PV-03	Change in packing/shipping specification	P / P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	*					

LOGISTICS / CAPACITY / TESTING - EQUIPMENT

	PAS-RES-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P / P	Change in process technique which is not already covered above. **Note:** Changes affecting the product not covered by the table require also a PCN.	e.g. new equipment supplier with different process concept	C					Test effort depends on final risk assessment. Performance test according to affected process change.
	PAS-RES-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	- / P	PCN required for dedicated equipment for sensitive component production.	e.g. additional equipment to increase production capacity e.g. replacement of same equipment	C					
	PAS-RES-EQ-03	Change in final test equipment type that uses a different technology	P / P	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C					Gage R&R / delta correlation

LOGISTICS / CAPACITY / TESTING - PROCESS FLOW

| | PAS-RES-PF-01 | Manufacturing site transfer or movement of a part of production process to a different location/site | P / P | Change of manufacturing site.
Note: Reorganization inside one plant/site is not affected | Movement or transfer of manufacturing site or process step(s) to a different location/site. | B | | | | | |
| | PAS-RES-PF-02 | Elimination or addition of a manufacturing process step | - / P | Change of manufacturing process sequence. | e.g. washing / cleaning process
e.g. change of order of processes | C | | | | | Characterisation depends on impact of production flow. |

LOGISTICS / CAPACITY / TESTING - Q-GATE

| | PAS-RES-QG-01 | Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling) | - / P | Change of test coverage. | e.g. change from 100% to sample inspection
e.g. test flow block, reduction from three to two temperature measurements
e.g. change in burn in/run in process. | C | | | | | R (elect. funct.): test coverage.
R (reliability) only for change in burn in process. |

INDUCTORS

ANY

| | PAS-IND-AN-01 | Any change with impact on special customer characteristics/contractual agreements | P / P | | | * | Not relevant for technical evaluation. | | | | |
| | PAS-IND-AN-02 | Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below. | P / P | | | B | Technical interface means component terminals. | | | | |

DATASHEET

	PAS-IND-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P / P	Change of application relevant information **Not included:** Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.				
	PAS-IND-DS-02	Correction of data sheet	I / P	No technical change of the product, only correction in description (wording, drawing, ...) **(I):** In case of editorial changes. **(P):** In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A					
	PAS-IND-DS-03	Specification of additional parameters	I / P	Description of a new not previously covered parameter. No technical change of the product. **(I):** no influence **(P):** Risk assessment depending on change for each application to provide evidence of additional parameter. (stat. evaluation)	e.g. adding new (tested) parameter.	A					

MATERIAL

Inductors / Ceramic / Tantalum — Change Classification Matrix

INDUCTORS — MATERIAL

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-IND-MA-01	Change of material composition - Bobbin Material	P	P	Material without magnetic function ("Spule/körper") typically made by plastic material	e.g. change from Thermoset to Thermoplastic	B	
PAS-IND-MA-02	Change of material composition - Core Material	P	P	Change of core material, which is material with magnetic function	e.g. change from NiZn into MnZn	A	
PAS-IND-MA-03	Change of material composition - Insulation Material	P	P	Change of insulation material	e.g. wire insulation, insulation tapes, e.g. change from Polyurethane to Polyamide	C	
PAS-IND-MA-04	Change of material composition - Lead Material	P	P	Change of lead material	e.g. change from tin coverd to non-coverd lead material	B	
PAS-IND-MA-05	Change of material composition - Mold Compound	P	P	Change of mold compound material	e.g. change to green mold	B	Electrical function affected if mechanical stress distribution changes. AOI, wave soldering and board coating has to be assessed. MSL might change.
PAS-IND-MA-06	Change of material composition - Solder Material	P	P	Change of solder material at internal connection.	e.g. change of SnAgCu composition	B	
PAS-IND-MA-07	Change of material composition - Wire / Foil Material	P	P	Wire for wounded inductors. Foil for multilayer inductors (inner electrode).	e.g. change of Cu composition	B	
PAS-IND-MA-08	Change of material composition - Glue	P	P	Change of glue material	e.g. change from glue A into glue B	C	Considers in case of core-core glue the air gap.
PAS-IND-MA-09	Change of supplier of material	-	P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C	Assumption material specification remains unchanged. Otherwise see change of material.
PAS-IND-MA-10	Change of material composition - Potting Material	P	P	Change of potting material	e.g. change from epoxy resin to silicon	C	A: If influence on other connections on PCB or laquer expected.

INDUCTORS — DESIGN

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-IND-DE-01	Changes of termination, surface finish, shape, color, appearance or dimension structure - Bobbin	I	P	Material without magnetic function ("Spule/körper") typically made by plastic material	e.g. construction / dimension change of bobbin	B	
PAS-IND-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead/Terminals	I	P	Change of lead/terminals	e.g. change from PTH terminals to SMD terminals	A	Effect regarding EMC relevant for high frequency only.
PAS-IND-DE-03	Changes of termination, surface finish, shape, color, appearance or dimension structure - Mold	I	P	Change of mold	e.g. new mold material with different colour	B	Parameter Analysis only for components where mold material has magnetic function
PAS-IND-DE-04	Change of inner construction - Core Construction	-	P	Change of core construction, which is material with magnetic function	e.g. change from drum core & shield core into pot core & cover plate core	A	
PAS-IND-DE-05	Change of inner construction - Insulation System	-	P	Change of insulation system	e.g. wire insulation, insulation tapes, e.g. change from Polyurethane to PTFE (Teflon)	C	
PAS-IND-DE-06	Change of inner construction - Wire / Foil Construction	-	P	Change of wire / foil dimensions	e.g. change from round cross section to rectangular cross section e.g. from single wire to litz wire	B	
PAS-IND-DE-07	Changes of termination, surface finish, shape, color, appearance or dimension structure - Potting Material	I	P	Change of potting dimension	e.g. change of potting (filling) height	C	If data sheet is affected (PAS-IND-DS-01)

INDUCTORS — PROCESS

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-IND-PR-01	Changes in process technology or manufacturing methods - Insulation Strip	-	P	(Mechanical) removal of insulation.	e.g. change from mechanical removal to laser removal	B	Mechanical damage of wire, impact on solderability in case of stripping process is affecting soldering area.
PAS-IND-PR-02	Changes in process technology or manufacturing methods - Lead Prep. / Plating	-	P	Change of lead prep. / plating	e.g. change from hot dip tinning to electroplating	B	Influence regarding reliability of solder joint.
PAS-IND-PR-03	Changes in process technology or manufacturing methods - Terminal Attach	-	P	Connection of wire terminal and / or connection of termination to core/bobbin.	e.g. chanfe from Manual winding to Semi-automtic winding (winding of wire on terminal)	C	Increase of contact resistance.
PAS-IND-PR-04	Changes in process technology or manufacturing methods - Marking	-	P	Change of marking process	e.g. change from ink marking to laser marking	B	
PAS-IND-PR-05	Changes in process technology or manufacturing methods - Molding	-	P	Change of molding process	e.g. change from one component molding to two component molding (other technology needed)	B	
PAS-IND-PR-06	Changes in process technology or manufacturing methods - Soldering Internal Connections	-	P	Change of soldering internal connection	e.g. change from hot tip tinning to resistance welding	B	
PAS-IND-PR-07	Changes in process technology or manufacturing methods - Winding Insulation	-	P	Change of winding - insulation	e.g. change from manual to automatic process	B	
PAS-IND-PR-08	Changes in process technology or manufacturing methods - Winding Wire	-	P	Change of winding - wire	e.g. change from semi-automatic winding to full automatic winding	C	
PAS-IND-PR-09	Process integrity: tuning within specification	-	P	Variation within process specification.	e.g. process control	C	
PAS-IND-PR-10	Changes in process technology or manufacturing methods - Potting	-	P	Change of potting process.	e.g. change from manual potting process to automatic potting process	C	

INDUCTORS — PACKING / SHIPPING – NEW MATERIAL, CRITICAL DIMENSIONS

ID	Description	T1	T2	Detail	Example	Class
PAS-IND-PN-01	Packing / shipping specification change (loosening of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B
PAS-IND-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B
PAS-IND-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier	e.g. change by material e.g. change by geometry.	B

INDUCTORS — PACKING / SHIPPING – VISUAL INSPECTION

ID	Description	T1	T2	Detail	Example	Class
PAS-IND-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(B) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	B
PAS-IND-PV-02	Change of product marking	I	P	Marking on device.	(B) e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B
PAS-IND-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	*

INDUCTORS — LOGISTICS / CAPACITY / TESTING – EQUIPMENT

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-IND-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes effecting the product not covered by the table require also a PCN.	e.g. introduction of potting process	C	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-IND-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. duplication of existing winding machine	C	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-IND-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C	Gage R&R / data correlation

INDUCTORS — LOGISTICS / CAPACITY / TESTING – PROCESS FLOW

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-IND-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one plant/site is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B	
PAS-IND-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	C	Characterisation depends on impact of production flow.
PAS-IND-PF-03	Elimination of final electrical measurement / test flow block	I	P	Reduction of final testing. PCN required for dedicated final test reductions for sensitive parameters.	e.g. elimination of High-voltage measurement	C	Characterisation depends on impact of final test flow.

INDUCTORS — LOGISTICS / CAPACITY / TESTING – Q-GATE

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-IND-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in process.	C	R (elecrt. funct.): test coverage. R (reliability) only for change in burn in process.

CERAMIC / TANTALUM — ANY

ID	Description	T1	T2	Detail	Example	Class
PAS-CER-AN-01	Any change with impact on special customer characteristics/contractual agreements	P	P		Not relevant for technical evaluation.	*
PAS-CER-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	P	P		Technical interface means component terminals.	B

CERAMIC / TANTALUM — DATASHEET

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-CER-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P	P	Change of application relevant information Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.
PAS-CER-DS-02	Correction of data sheet	I	P	No technical change of the product, only correction in description (wording, drawing, ...) (I): In case of editorial changes. (P): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A	
PAS-CER-DS-03	Specification of additional parameters	I	P	Description of a new not previously covered parameter. No technical change of the product. (I): no influence (P): Risk assessment depending on change for each application to provide evidence of additional parameter. (stat. evaluation)	e.g. adding new (tested) parameter.	A	

CERAMIC / TANTALUM — MATERIAL

ID	Description	T1	T2	Detail	Example	Class	Notes
PAS-CER-MA-01	Change of material composition - Ceramic Binder	P	P	Binder material (ceramic)		C	
PAS-CER-MA-02	Change of material composition - Tantalum Binder	P	P	Binder material (tantal)	e.g. change from wax 1 to wax 2	C	
PAS-CER-MA-03	Change of material composition - Dielectric	P	P	Dielectric change (ceramic only)	e.g. change from ceramic A into ceramic B	C	
PAS-CER-MA-04	Change of material composition - Electrode Attach	P	P	Electrode attach (only tantal, glue, carbon, Ag)	e.g. change of Ag particle size in conductive adhesive	C	
PAS-CER-MA-05	Change of material composition - Electrode Material	P	P	Electrode Material (only ceramic, inner electrode)	e.g. change from spheric to flake shape (Ni paste)	C	
PAS-CER-MA-06	Change of material composition - Encapsulation	P	P	Encapsulation	e.g. change from epoxy1 into epoxy2	C	Check whether AOI at Tier 1 can be affected
PAS-CER-MA-07	Change of material composition - Lead material / Termination	P	P	Lead material / Termination.	e.g. change from SnPb to pure Sn	C	

Category	Code	Change description	Change details	Example	Class
CERAMIC / TANTALUM	PAS-CER-MA-08	Change of supplier of material	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C
CERAMIC / TANTALUM	**DESIGN**				
CERAMIC / TANTALUM	PAS-CER-DE-01	Change of termination, surface finish, shape, color, appearance or dimension structure - Lead Diameter	Lead diameter	e.g. change from 0.8mm into 0.6mm	B
CERAMIC / TANTALUM	PAS-CER-DE-02	Change of termination, surface finish, shape, color, appearance or dimension structure - Termination Area	Termination area	e.g. change in width of termination from 0.1 -0.3mm into 0.2 - 0.4 mm	B
CERAMIC / TANTALUM	PAS-CER-DE-03	Change of termination, surface finish, shape, color, appearance or dimension structure - Terminal interface	Terminal interface	e.g. additional layer in termination	B
CERAMIC / TANTALUM	PAS-CER-DE-04	Changes of inner construction - Electrode Thickness	Electrode thickness (ceramic only)	e.g. Ni layer change from 2.5µm into 3.5µm	C
CERAMIC / TANTALUM	PAS-CER-DE-05	Changes of inner construction - Layer Thickness	Layer thickness (dielectric thickness)	e.g. Ceramic layer thickness changes from 3µm into 5µm.	C
CERAMIC / TANTALUM	PAS-CER-DE-06	Changes of inner construction - Number of Layers	Number of layers (ceramic only). Always in combination with PAS-CER-DE-05.	see also layer thickness	C
CERAMIC / TANTALUM	**PROCESS**				
CERAMIC / TANTALUM	PAS-CER-PR-01	Changes in process technology or manufacturing methods - Dicing	Change of dicing	e.g. change from cutting to sawing	C
CERAMIC / TANTALUM	PAS-CER-PR-02	Changes in process technology or manufacturing methods - Electrode apply	Electrode apply (dielectric layer process)	e.g. change from wet to dry process	C
CERAMIC / TANTALUM	PAS-CER-PR-03	Changes in process technology or manufacturing methods - Firing	Change of firing profile	e.g. seperation of decarbonization and firing profile.	C
CERAMIC / TANTALUM	PAS-CER-PR-04	Changes in process technology or manufacturing methods - Lamination	Change of lamination / press technique	e.g. standard pressing to iso static pressing.	C
CERAMIC / TANTALUM	PAS-CER-PR-05	Changes in process technology or manufacturing methods - Particle Size	Change of powder particle size. Always in combination with PAS-CER-MA-03.	e.g. change D50 from 0.5µm into 0.4µm	C
CERAMIC / TANTALUM	PAS-CER-PR-06	Changes in process technology or manufacturing methods - Screening/Printing	Change of screening / printing	e.g. change from screen printing into offset printing	C
CERAMIC / TANTALUM	PAS-CER-PR-07	Changes in process technology or manufacturing methods - Termination	Change for termination preparation like plating or apply of termination base layer.	e.g. change in plating technology (final termination) e.g. change from dip in paste to plating (apply)	B
CERAMIC / TANTALUM	PAS-CER-PR-08	Process integrity: tuning within specification	Variation within process specification.	e.g. process control	C
CERAMIC / TANTALUM	**PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS**				
CERAMIC / TANTALUM	PAS-CER-PN-01	Packing / shipping specification change (loosening of tolerances)	Change of packing specification.	e.g. number of pieces on reel.	B
CERAMIC / TANTALUM	PAS-CER-PN-02	Dry pack requirements change	Change of drypack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B
CERAMIC / TANTALUM	PAS-CER-PN-03	Change of carrier (tray, reel)	Change of carrier	e.g. change by material e.g. change by geometry.	B
CERAMIC / TANTALUM	**PACKING / SHIPPING - VISUAL INSPECTION**				
CERAMIC / TANTALUM	PAS-CER-PV-01	Change of labelling	Change of labelling, also on reel.	(B) e.g. additional information (RoHS stamp) (PI) e.g. change of customer specific information	B
CERAMIC / TANTALUM	PAS-CER-PV-02	Change of product marking	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B
CERAMIC / TANTALUM	PAS-CER-PV-03	Change of packing/shipping specification	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	*
CERAMIC / TANTALUM	**LOGISTICS / CAPACITY / TESTING - EQUIPMENT**				
CERAMIC / TANTALUM	PAS-CER-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. change from wet to dry technology.	C
CERAMIC / TANTALUM	PAS-CER-EQ-02	Production from a new equipment/tool which use the same basic technology (replacement equipment or extension of existing equipment pool)	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	C
CERAMIC / TANTALUM	PAS-CER-EQ-03	Change in final test equipment type that uses a different technology	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C
CERAMIC / TANTALUM	**LOGISTICS / CAPACITY / TESTING - PROCESS FLOW**				
CERAMIC / TANTALUM	PAS-CER-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	Change of manufacturing site. Note: Reorganization inside one plant/site is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B
CERAMIC / TANTALUM	PAS-CER-PF-02	Elimination or addition of a manufacturing process step	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	C
CERAMIC / TANTALUM	**LOGISTICS / CAPACITY / TESTING - Q-GATE**				
CERAMIC / TANTALUM	PAS-CER-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	C
Film capacitors	**Film capacitors**				
Film capacitors	**Any**				
Film capacitors	PAS-FLM-AN-01	Any change with impact on special customer characteristics/contractual agreements		Not relevant for technical evaluation.	*
Film capacitors	PAS-FLM-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.		Technical interface means component terminals.	B
Film capacitors	**DATASHEET**				
Film capacitors	PAS-FLM-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	Change of application relevant information Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A
Film capacitors	PAS-FLM-DS-02	Correction of data sheet	No technical change of the product, only correction in description (wording, drawing, ...) (B): In case of editorial changes. (PI): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A
Film capacitors	PAS-FLM-DS-03	Specification of additional parameters	Description of a new not previously covered parameter. No technical change of the product. (B): no influence (PI): Risk assessment depending on change for each application to provide existence of additional parameter (stat. evaluation)	e.g. adding new (tested) parameter.	A
Film capacitors	**MATERIAL**				
Film capacitors	PAS-FLM-MA-01	Change of material composition - Sealing Compound	Typically change within epoxy or PU sealing without effect to mechanical properties. Note: Change from epoxy sealing into PU sealing (both direction) will lead to generate a new product.	e.g. change of epoxy or PU composition	C
Film capacitors	PAS-FLM-MA-02	Change of material composition - Package	Change material of package.	Change material of package, e.g. change from PBT to PPS e.g. change of glas fiber ratio	B
Film capacitors	PAS-FLM-MA-03	Change of material composition - Lead/Termination	Change of Lead/Termination Note: If change of lead frame material leads to an ESR change, then change of data sheet (PAS-FLM-DS-01) has to be respected.	e.g. change of basis material from Cu to Fe e.g. change of finishing from SnPb to Sn	B
Film capacitors	PAS-FLM-MA-04	Change of material composition - Metal Spray (Schoop)	Change of Metal Spray (Schoop): Use different material for metal spray process for boxed and naked types	e.g. from Zn to Al	C
Film capacitors	PAS-FLM-MA-05	Change of material composition - Film	Change of film material for boxed and naked types	e.g. change of additives (<1%) of film composition (same raw material)	C
Film capacitors	PAS-FLM-MA-06	Change of material composition - Metal Foil	Change of metal foil for inner electrode	e.g. change from Al to Al-Zn alloy	C
Film capacitors	PAS-FLM-MA-07	Change to a new or additional material supplier at component manufacturer which are described above.		e.g. for 2nd source purpose	C
Film capacitors	**DESIGN**				
Film capacitors	PAS-FLM-DE-01	Change of termination, surface finish, shape, color, appearance or dimension structure - Lead Diameter / Thickness	Change of lead diameter thickness	e.g. change lead diameter from 0.5 to 0.4 mm e.g. change of thickness of terminal	B
Film capacitors	PAS-FLM-DE-02	Change of termination, surface finish, shape, color, appearance or dimension structure - Termination Area	Changes of termination area are changes which are affecting the area for connection of component and PCB	e.g. change of termination layer thickness. e.g. change in termination dimensions / shape	B
Film capacitors	PAS-FLM-DE-03	Change of inner construction - Inner Connection	Change of inner connection	e.g. change from soldered connection to welded connection	C
Film capacitors	PAS-FLM-DE-04	Change of termination, surface finish, shape, color, appearance or dimension structure - Appearance	Change of appearance. (B): Change in appearance without impact on product integrity. (PI): Change in appearance with impact on product integrity. Note: Marking on device is defined as seperate change (PAS-FLM-PV-02).	e.g. change or adding of colour on component	B
Film capacitors	PAS-FLM-DE-05	Change of inner construction - Film/Foil	Change of film or foil design	e.g. change to a different foil supplier.	C
Film capacitors	PAS-FLM-DE-06	Change of inner construction - Insulation System	Change of inner insulation to protect winding element against housing.	e.g. change of potting material e.g. change of number of inner insulation layers (depending of insulation material thickness)	C
Film capacitors	PAS-FLM-DE-07	Change of termination, surface finish, shape, color, appearance or dimension structure - Packaging	Change of packaging	e.g. change of dimension or shape e.g. change of surface	B
Film capacitors	**PROCESS**				
Film capacitors	PAS-FLM-PR-01	Changes in process technology or manufacturing methods - Package	Change of resin filling or hardening process (relevant for boxed types only)	e.g. change in resin filling process (mixing, sequence, potting, ...) e.g. change in hardening process (temperature, ...)	C
Film capacitors	PAS-FLM-PR-02	Changes in process technology or manufacturing methods - Terminal Attach	Change Terminal Attach Process to winding element for boxed and nacked types	e.g. spraying and / or galvanic process, e.g. welding / soldering	B
Film capacitors	PAS-FLM-PR-03	Changes in process technology or manufacturing methods - Winding	Change of winding, flattening or tempering process	e.g. change of tempering temperature	C

Category	ID	Description	I/P	P	Detail	Example	Class	Notes
Film capacitors	PAS-FLM-PR-04	Process integrity: tuning within specification	-	P	Variation within process specification.	e.g. process control	C	
Film capacitors		**PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS**						
Film capacitors	PAS-FLM-PN-01	Packing / shipping specification change (loosening of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B	
Film capacitors	PAS-FLM-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B	
Film capacitors	PAS-FLM-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier	e.g. change by material e.g. change by geometry.	B	
Film capacitors		**PACKING / SHIPPING - VISUAL INSPECTION**						
Film capacitors	PAS-FLM-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(I) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	B	
Film capacitors	PAS-FLM-PV-02	Change of product marking	I	P	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B	
Film capacitors	PAS-FLM-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	-	
Film capacitors		**LOGISTICS / CAPACITY / TESTING - EQUIPEMENT**						
Film capacitors	PAS-FLM-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. implementation of new machines	C	Test effort depends on final risk assessment. Performance test according to affected process change.
Film capacitors	PAS-FLM-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. extension of existing machin capacity	C	Test effort depends on final risk assessment. Performance test according to affected process change.
Film capacitors	PAS-FLM-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C	Gage R&R / data correlation
Film capacitors		**LOGISTICS / CAPACITY / TESTING - PROCESS FLOW**						
Film capacitors	PAS-FLM-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one plant/site is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B	
Film capacitors	PAS-FLM-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes.	C	Characterisation depends on impact of production flow.
Film capacitors		**LOGISTICS / CAPACITY / TESTING - Q-GATE**						
Film capacitors	PAS-FLM-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	C	R (elect. func.) / test coverage. R (reliability) only for change in burn in process.
QUARTZ CRYSTAL / SAW		**QUARTZ CRYSTAL / SAW**						
QUARTZ CRYSTAL / SAW		**ANY**						
QUARTZ CRYSTAL / SAW	PAS-QUA-AN-01	Any change with impact on special customer characteristics/contractual agreements	P	P		Not relevant for technical evaluation.	-	
QUARTZ CRYSTAL / SAW	PAS-QUA-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	P	P		Technical interface means component terminals.	B	
QUARTZ CRYSTAL / SAW		**DATASHEET**						
QUARTZ CRYSTAL / SAW	PAS-QUA-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P	P	Change of application relevant information. Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.
QUARTZ CRYSTAL / SAW	PAS-QUA-DS-02	Correction of data sheet	I	P	No technical change of the product, only correction in description (wording, drawing, ...) (I): In case of editorial changes. (P): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A	
QUARTZ CRYSTAL / SAW	PAS-QUA-DS-03	Specification of additional parameters	I	P	Description of a new not previously covered parameter. No technical change of the product. (I): no influence (P): Risk assessment depending on change for each application to provide existence of additional parameters (test evaluation)	e.g. adding new (tested) parameter.	A	
QUARTZ CRYSTAL / SAW		**MATERIAL**						
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-01	Change of material composition - Quartz Blank	P	P	A change of Quartz Blank is a very rare case. Mainly for SAW-Filter		A	
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-02	Change of material composition - Base	P	P	Changing of the material of the base.	e.g. change from ceramic to epoxy	A	CO may be influenced. Temperature expansion coefficient may change
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-03	Change of material composition - Lead / Termination	P	P	Change of Lead/Termination	e.g. change of plating finish. (eg Au, AgPd,Sn)	B	
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-04	Change of material composition - Sealing	P	P	Change of Glass Seal	e.g. change to lead free glass	B	X-Ray inspection may be influenced when sealing is containing Pb
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-05	Change of material composition - Can / Cap	P	P	Changing of the material of the can/cap	e.g. change from metal to ceramic material	A	
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-06	Change of material composition - Blank Support	P	P	Change Blank Support	e.g. change of glue (Silicone to Epoxy) e.g. change metal holders (old base)	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-07	Change of material composition - Overmold	P	P	Change of Overmold	e.g. change to green mold compound e.g. change of filler particles	B	Electrical function affected in case of mechanical stress distribution change. AOI, wave soldering and board coating has to be assessed. MSL might be changed.
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-08	Change of material composition - Case Sealing	P	P	Change of Case Sealing. Change of material for seam welding. Relevant for components with ceramic base and metal cap.	e.g. change from solder paste to adhesive glue	C -	Impedance my be influenced.
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-09	Change of material composition - Electrode	P	P	Change of Electrode material on crystal blank.	e.g. change from Au to Ag	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-10	Change of material composition - Insulator	P	P	Change of Insulator. Only for leaded types. Not relevant for typical SMD.	e.g. insulating plate under crystal e.g. Glass sealing for leads	B	
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-11	Change of material composition - Marking	P	P	Change of marking material	e.g. change of ink e.g. chemical to environmental friendly	B	AOI check necessary!
QUARTZ CRYSTAL / SAW	PAS-QUA-MA-12	Change of supplier of material	-	P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose.	C	Assumption material specification remains unchanged. Otherwise see change of material.
QUARTZ CRYSTAL / SAW		**DESIGN**						
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-01	Change of termination, surface finish, shape, color, appearance or dimension structure - Base	I	P	Change of Base design	e.g. due to miniaturization purpose.	B	
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-02	Change of termination, surface finish, shape, color, appearance or dimension structure - Lead / Termination	I	P	Change of Lead/Termination design. Change geometry or terminal pad or lead design / new technology	e.g. change lead design to improve reliability.	B	CO may be influenced Reliability of solder joints may be affected
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-03	Change of termination, surface finish, shape, color, appearance or dimension structure - Can / Cap	I	P	Change of Can/Cap design	e.g. due to miniaturization purpose.	A	
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-04	Change of termination, surface finish, shape, color, appearance or dimension structure - Package	I	P	Change of Package (Molded). Change the design of the package. Not relevant for typical SMD.	e.g. change from welded device to glued device (case sealing)	B	Electrical function affected in case of mechanical stress distribution change. AOI, wave soldering and board coating has to be assessed. MSL might be changed.
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-05	Change of termination, surface finish, shape, color, appearance or dimension structure - Insulator	I	P	Change of Insulator design. Only for leaded types (old technology) Not relevant for typical SMD.		B	
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-06	Change of inner construction - Quartz Blank	-	P	Change of Quartz Blank design	e.g. change dimension of blank, add phase, electrode design, ...	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-DE-07	Change of inner construction - Blank Support	-	P	Change Blank Support design	e.g. change design of glue shape e.g. change design of metal supporter	C	
QUARTZ CRYSTAL / SAW		**PROCESS**						
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-01	Changes in process technology or manufacturing methods - Quartz Blank	-	P	Change of Quartz Blank process	e.g. change of cutting or lapping technology	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-02	Changes in process technology or manufacturing methods - Blank Etching / Cleaning	-	P	Change of Blank Etch/Clean process (along different / new technology)	e.g. change from liquid etching to plasma etching	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-03	Changes in process technology or manufacturing methods - Electrode Formation	-	P	Change of Electrode Formation process	e.g. change from evaporation to sputtering	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-04	Changes in process technology or manufacturing methods - Trimming	-	P	Change of Auto Trim process (Method of final frequency tuning)	e.g. change from evaporation to ion beam	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-05	Changes in process technology or manufacturing methods - Bonding / Annealing	-	P	Change of Blank bonding / annealing process. Change of method how apply conductive material to base or blank		C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-06	Changes in process technology or manufacturing methods - Can / Cap Attaching	-	P	Change of Cap/Can attaching process	e.g. change of the sealing method e.g. change from batch oven to reflow oven	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-07	Changes in process technology or manufacturing methods - Molding	-	P	Change of Overmolding process. Not relevant for typical SMD.	e.g. change of overmold process parameter	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-08	Changes in process technology or manufacturing methods - Marking	-	P	Change of Marking process	e.g. change from inked marking to laser marking e.g. marking of pin 1 e.g. change of appearance (additional marking)	B	AOI check necessary!
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-09	Changes in process technology or manufacturing methods - Aging	-	P	Change of Aging process. Typically no aging done on quartz crystals.	If aging is done: e.g. change of times or temperatures	C	
QUARTZ CRYSTAL / SAW	PAS-QUA-PR-10	Process integrity: tuning within process specification	-	P	Variation within process specification.	e.g. process control	C	
QUARTZ CRYSTAL / SAW		**PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS**						
QUARTZ CRYSTAL / SAW	PAS-QUA-PN-01	Packing / shipping specification change (loosening of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B	

Category	ID	Description	I/P	P	Change	Example	Class	Risk assessment note	Far-right note
QUARTZ CRYSTAL / SAW	PAS-QUA-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL, e.g. change in dry pack assurance (HIC, MBB)	B		
QUARTZ CRYSTAL / SAW	PAS-QUA-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier	e.g. change by material, e.g. change by geometry.	B		
PACKING / SHIPPING - VISUAL INSPECTION									
QUARTZ CRYSTAL / SAW	PAS-QUA-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(I) e.g. additional information (RoHS stamp), (P) e.g. change of customer specific information	B		
QUARTZ CRYSTAL / SAW	PAS-QUA-PV-02	Change of product marking	I	P	Marking on device.	e.g. change of content of marking, e.g. change of method of marking, e.g. change of appearance of marking	B		
QUARTZ CRYSTAL / SAW	PAS-QUA-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	-		
LOGISTICS / CAPACITY / TESTING - EQUIPMENT									
QUARTZ CRYSTAL / SAW	PAS-QUA-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. new equipment supplier with different process concept	C		Test effort depends on final risk assessment. Performance test according to affected process change.
QUARTZ CRYSTAL / SAW	PAS-QUA-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. additional equipment to increase production capacity, e.g. replacement of same equipment	C		Test effort depends on final risk assessment. Performance test according to affected process change.
QUARTZ CRYSTAL / SAW	PAS-QUA-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C		Gage R&R / delta correlation
LOGISTICS / CAPACITY / TESTING - PROCESS FLOW									
QUARTZ CRYSTAL / SAW	PAS-QUA-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one site/rule is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B		
QUARTZ CRYSTAL / SAW	PAS-QUA-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process, e.g. change of order of processes	C		Characterisation depends on impact of production flow.
LOGISTICS / CAPACITY / TESTING - Q-GATE									
QUARTZ CRYSTAL / SAW	QUA-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection, e.g. test flow block, reduction from three to two temperature measurements, e.g. change in burn in/run in process.	C		R (elect. funct.): test coverage. R (reliability): only for change in burn in process.
Aluminium Electrolytic Capacitor									
Al-Cap		**Any**							
Al-Cap	PAS-ALU-AN-01	Any change with impact on special customer characteristics/contractual agreements	P	P		Not relevant for technical evaluation.	-		
Al-Cap	PAS-ALU-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	P	P		Technical interface means component terminals. See processability on board level.	B		
DATASHEET									
Al-Cap	PAS-ALU-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P	P	Change of application relevant information. Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.	
Al-Cap	PAS-ALU-DS-02	Correction of data sheet	I	P	No technical change of the product, only correction in description (wording, drawing, ...). (I): In case of editorial changes. (P): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A		
Al-Cap	PAS-ALU-DS-03	Specification of additional parameters	I	P	Description of a new not previously covered parameter. No technical change of the product. (I): no influence. (P): Risk assessment depending on change for each application to provide evidence of additional parameter. (stat. evaluation)	e.g. adding new (tested) parameter.	A		
MATERIAL									
Al-Cap	PAS-ALU-MA-01	Change of material composition - Housing	P	P	Change of housing	e.g. change Al alloy for housing	C		
Al-Cap	PAS-ALU-MA-02	Change of material composition - Sealing	P	P	Change of sealing	e.g. change of rubber compound, e.g. change of sealing disc material (axial, Snap in)	C	B: in case of external surface of sealing is changed. Evaluation only, if capacitor is glued	
Al-Cap	PAS-ALU-MA-03	Change of material composition - External insulation	P	P	Change of external insulation / sleeving	e.g. change from PVC into PET, e.g. change of colour	C	B: Only for glued capacitors.	
Al-Cap	PAS-ALU-MA-04	Change of material composition - Lead / Termination	P	P	Change of lead or outer termination.	e.g. change of leadframe from iron into copper, e.g. change of leadframe finish from tin/lead into tin	B		Biased Humidity test can be done without applying voltage.
Al-Cap	PAS-ALU-MA-05	Change of material composition - Internal Insulation / Paper	P	P	Change of paper type / internal insulation	e.g. change of paper thickness 50 µm to 40µm	C	A: Only if impedance increase (delta characterization). Check if datasheet is affected (PAS-ALU-DS-01).	
Al-Cap	PAS-ALU-MA-06	Change of material composition - Electrolyte	P	P	Change of electrolyte	e.g. change in formulation	C	A: Only if impedance increase (delta characterization). Check if datasheet is affected (PAS-ALU-DS-01).	
Al-Cap	PAS-ALU-MA-07	Change of material composition - Tape Material	P	P	Change of closing tape material	e.g. change of glue or basic material	C		
Al-Cap	PAS-ALU-MA-08	Change of material composition - Base Plate	P	P	Change of base plate material	e.g. change of used plastic material	B		
Al-Cap	PAS-ALU-MA-09	Change of supplier of material	-	P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C		Test effort depends on final risk assessment. Performance test according to affected material. Assumption material specification remains unchanged. Otherwise see change of material.
DESIGN									
Al-Cap	PAS-ALU-DE-01	Change of termination, surface finish, shape, color, appearance or dimension structure - Wire Diameter	I	P	Change of wire diameter	e.g. change from 0.8 into 0.6 mm diameter.	B		
Al-Cap	PAS-ALU-DE-02	Change of termination, surface finish, shape, color, appearance or dimension structure - Termination	-	P	Change of termination appearance. For welded Al capacitors only.	e.g. change from matt tin into bright tin.	B		
Al-Cap	PAS-ALU-DE-03	Change of termination, surface finish, shape, color, appearance or dimension structure - Appearance	I	P	Change of appearance Note: Marking on device is defined as separate change (PAS-ALU-PV-02).	e.g. change of colour/appearance, e.g. change of safety vent shape	B		
Al-Cap	PAS-ALU-DE-04	Change of termination, surface finish, shape, color, appearance or dimension structure - Rubber Sealing	I	P	Change of rubber sealing stand-off shape (for radial)	e.g. change of profile / design	A		
Al-Cap	PAS-ALU-DE-05	Change of inner construction - Aluminum Foil	-	P	Change of Al foil width	e.g. change of width	C		
Al-Cap	PAS-ALU-DE-06	Change of inner construction - Separator	-	P	Change of seperator width	e.g. change of width	C		
Al-Cap	PAS-ALU-DE-07	Change of inner construction - Separator Density	-	P	Change of seperator density	e.g. change of separator density/resistivity	C		
Al-Cap	PAS-ALU-DE-08	Change of inner construction - Inner Connection	-	P	Change of inner connection	e.g. change of shape/dimension	C		Terminal Strength (11) not for axial components without paddle tabs.
Al-Cap	PAS-ALU-DE-09	Change of inner construction - Closing Tape	-	P	Change of closing tape	e.g. change of dimension	C		
Al-Cap	PAS-ALU-DE-10	Change of inner construction - Foil	-	P	Change of foil type	e.g. change of etching level, e.g. change of thickness	C		
PROCESS									
Al-Cap	PAS-ALU-PR-01	Changes in process technology or manufacturing methods - Terminal Attach	-	P	Change of terminal attach process	e.g. change of stitching / welding layout	C		Terminal Strength (11) and Vibration (14) not for axial components without paddle tabs.
Al-Cap	PAS-ALU-PR-02	Changes in process technology or manufacturing methods - Winding	-	P	Change of winding process	e.g. change of material disposition	B	A: only for HV application	Surge voltage test for high voltage components only.
Al-Cap	PAS-ALU-PR-03	Changes in process technology or manufacturing methods - Impregnation	-	P	Change of impregnation	e.g. change of bulk process into individual impregnation	C		
Al-Cap	PAS-ALU-PR-04	Changes in process technology or manufacturing methods - Assembly	-	P	Change of assembly process	e.g. change of sealing method, e.g. change of assembly process sequence	C		R: Depends on process change
Al-Cap	PAS-ALU-PR-05	Changes in process technology or manufacturing methods - Aging / Testing	-	P	Change of aging/testing process	e.g. change of timing, voltage or temperature of process	C		R: Depends on process change
Al-Cap	PAS-ALU-PR-06	Changes in process technology or manufacturing methods - Trim & Form Leaded	-	P	Change of trim & form process (leaded)	e.g. change of tooling shape or bending procedure	B		Solderability may be influenced
Al-Cap	PAS-ALU-PR-07	Changes in process technology or manufacturing methods - Trim & Form SMD	-	P	Change of trim & form process (SMD)	e.g. change of tooling shape or bending procedure	B		Solderability may be influenced
Al-Cap	PAS-ALU-PR-08	Process integrity: tuning within specification	-	P	Variation within process specification.	e.g. process control	C		
PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS									
Al-Cap	PAS-ALU-PN-01	Packing / shipping specification (lowering of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B		
Al-Cap	PAS-ALU-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL, e.g. change in dry pack assurance (HIC, MBB)	B		
Al-Cap	PAS-ALU-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier	e.g. change by material, e.g. change by geometry.	B		
PACKING / SHIPPING - VISUAL INSPECTION									
Al-Cap	PAS-ALU-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(I) e.g. additional information (RoHS stamp), (P) e.g. change of customer specific information	B		
Al-Cap	PAS-ALU-PV-02	Change of product marking	I	P	Marking on device.	e.g. change of content of marking, e.g. change of method of marking, e.g. change of appearance of marking	B		
Al-Cap	PAS-ALU-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	-		
LOGISTICS / CAPACITY / TESTING - EQUIPEMENT									
Al-Cap	PAS-ALU-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. new equipment supplier with different process concept	C		Test effort depends on final risk assessment. Performance test according to affected process change.
Al-Cap	PAS-ALU-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. additional equipment to increase production capacity, e.g. replacement of same equipment	C		Test effort depends on final risk assessment. Performance test according to affected process change.

Al-Cap

ID	Description	I	P	Detail	Example	Class	Remark
PAS-ALU-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. Note: PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C	Gage R&R / delta correlation

LOGISTICS / CAPACITY / TESTING - PROCESS FLOW

ID	Description	I	P	Detail	Example	Class	Remark
PAS-ALU-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one plantsite is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B	
PAS-ALU-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	C	Characterisation depends on impact of production flow.
PAS-ALU-PF-03	Elimination of final electrical measurement / test flow block	I	P	Reduction of final testing. PCN required for dedicated final test reductions for sensitive parameters.	e.g. elimination of additional impedance-control	C	Characterisation depends on impact of final test flow.

LOGISTICS / CAPACITY / TESTING - Q-GATE

ID	Description	I	P	Detail	Example	Class	Remark
PAS-ALU-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	C	R (elect. funct.): test coverage. R (reliability) only for change in burn in process.

NTC

Any

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-AN-01	Any change with impact on special customer characteristics/contractual agreements.	P	P		Not relevant for technical evaluation.	*	
PAS-NTC-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	P	P		Technical interface means component terminals.	B	

DATASHEET

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P	P	Change of application relevant information Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.
PAS-NTC-DS-02	Correction of data sheet	I	P	No technical change of the product, only correction in description (wording, drawing, ...). (I): In case of editorial changes. (P): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A	
PAS-NTC-DS-03	Specification of additional parameters.	I	P	Description of a new not previously covered parameter. No technical change of the product. (I): no influence (P): Risk assessment depending on change for each application to provide evidence of additional parameter. (stat. evaluation)	e.g. adding new (tested) parameter.	A	

MATERIAL

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-MA-01	Change of material composition - Ceramic Binder	P	P	Change of Binder Material to bind ceramic.		C	
PAS-NTC-MA-02	Change of material composition - Ceramic	P	P	Change of ceramic composition	e.g. changes in additives amount	C	Parameter analyse only necessary if an anticipated impact on electrical performance. S = SMD device only
PAS-NTC-MA-03	Change of material composition - Inner Electrode	P	P	Change of inner electrode material (ink material). Valid in case of multilayer structures only.	e.g. change from AgPt material to AgPd material	C	Parameter analyse only necessary if an anticipated impact on electrical performance.
PAS-NTC-MA-04	Change of material composition - Encapsulation	P	P	Change of encapsulation material.	e.g. change of coating e.g. change of additives in an insulation.	B	A: Risk assessment on application level, if interaction with other material expected.
PAS-NTC-MA-05	Change of material composition - Lead material / Termination	P	P	Change of lead or outer termination. Change of lead (finish) material, termination material or attachment material.	e.g. change from SnPb to pure Sn.	B	Risk assessment needed to evaluate compatibility of soldering process.
PAS-NTC-MA-06	Change of supplier of material	-	P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C	Assumption material specification remains unchanged. Otherwise see change of material.

DESIGN

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-DE-01	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead Diameter	I	P	Change of lead diameter	e.g. change lead diameter from 0.5 to 0.4 mm	B	
PAS-NTC-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure - Termination Area	I	P	Change of termination area	e.g. change of termination layer thickness e.g. change in termination dimensions	B	SMD components only!
PAS-NTC-DE-03	Changes of termination, surface finish, shape, color, appearance or dimension structure - Internal Connection	I	P	Change of inner connection	e.g. change from soldered connection to welded connection	C	
PAS-NTC-DE-04	Changes of termination, surface finish, shape, color, appearance or dimension structure - Appearance	I	P	Change of appearance. Note: Marking on device is defined as separate change (PAS-PLM-PV-02).	e.g. change or adding of colour on component Mainly in combination with other changes!	B	
PAS-NTC-DE-05	Change of inner construction - Electrode	-	P	Change of electrode layer thickness or geometry. For multi-layer technology only.	e.g. change of electrode design	C	
PAS-NTC-DE-06	Change of inner construction - Layer Thickness	-	P	Change of ceramic layer thickness. For multi-layer technology only.	e.g. change from 1.5µm into 1.0µm	C	
PAS-NTC-DE-07	Change of inner construction - Number of Layers	-	P	Change of number of ceramic or electrode layers. For multi-layer technology only. Always in combination with PAS-NTC-DE-06.	see also layer thickness	C	

PROCESS

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-PR-01	Changes in process technology or manufacturing methods - Lamination	-	P	Change of lamination / press technique technology	e.g. stamp press to isostatic press	C	
PAS-NTC-PR-02	Changes in process technology or manufacturing methods - Firing	-	P	Change of firing / sintering profile	e.g. temperature and / or time and / or atmosphere. e.g. from tunnel to batch kiln.	C	
PAS-NTC-PR-03	Changes in process technology or manufacturing methods - Dicing	-	P	Change of dicing / slicing	e.g. change from cutting to sawing	C	
PAS-NTC-PR-04	Changes in process technology or manufacturing methods - Termination	-	P	Change for termination preparation like plating or apply of termination base layer.	e.g. change in plating technology (final termination) e.g. change from dip in paste to plating (apply)	B	
PAS-NTC-PR-05	Changes in process technology or manufacturing methods - Electrode apply	-	P	Change of electrode apply. For multi layer technology only.	e.g. change of inner electrode lay down method.	C	
PAS-NTC-PR-06	Changes in process technology or manufacturing methods - Assembly	-	P	Change in assembly process for leaded or encapsulated devices.	e.g. soldering method for lead attach to element or coating / encapsulation process	B	
PAS-NTC-PR-07	Process integrity: tuning within specification	-	P	Variation within process specification	e.g. process control	C	

PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-PN-01	Packing / shipping specification change (loosening of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B	
PAS-NTC-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B	
PAS-NTC-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier	e.g. change by material e.g. change by geometry.	B	

PACKING / SHIPPING - VISUAL INSPECTION

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(I) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	B	
PAS-NTC-PV-02	Change of product marking	I	P	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B	
PAS-NTC-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	*	

LOGISTICS / CAPACITY / TESTING - EQUIPEMENT

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. change from wet to dry technology.	C	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-NTC-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	C	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-NTC-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. Note: PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C	Gage R&R / delta correlation

LOGISTICS / CAPACITY / TESTING - PROCESS FLOW

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one plantsite is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B	
PAS-NTC-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	C	Characterisation depends on impact of production flow.

LOGISTICS / CAPACITY / TESTING - Q-GATE

ID	Description	I	P	Detail	Example	Class	Remark
PAS-NTC-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	C	Characterisation depends on impact of test coverage. R (elect. funct.): test coverage. R (reliability) only for change in burn in process.

PTC

Any

ID	Description	I	P	Detail	Example	Class	Remark
PAS-PTC-AN-01	Any change with impact on special customer characteristics/contractual agreements.	P	P		Not relevant for technical evaluation.	*	
PAS-PTC-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	P	P		Technical interface means component terminals. See processability on board level.	B	

DATASHEET

ID	Description	I	P	Detail	Example	Class	Remark
PAS-PTC-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P	P	Change of application relevant information Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.

ID	Description			Notes	Example	Class	Risk assessment note	Remarks
PAS-PTC-DS-02	Correction of data sheet	I	P	No technical change of the product, only correction in description (wording, drawing, ...). (I): In case of editorial changes. (P): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A		
PAS-PTC-DS-03	Specification of additional parameters	I	P	Description of a new not previously covered parameter. No technical change of the product. (I): no influence (P): Risk assessment depending on change for each application to provide evidence of additional parameter (stat. evaluation)	e.g. adding new (tested) parameter.	A		
MATERIAL								
PAS-PTC-MA-01	Change of material composition - Ceramic Binder	P	P	Change of Binder Material to bind ceramics.		C		
PAS-PTC-MA-02	Change of material composition - Ceramic	P	P	Change of ceramic composition	e.g. changes in additives amount	C		Parameter analyse only necessary if an anticipated impact on electrical performance. S = SMD device only
PAS-PTC-MA-03	Change of material composition - Polymer	P	P	Change of polymer composition		C		
PAS-PTC-MA-04	Change of material composition - Encapsulation	P	P	Change of encapsulation material.	e.g. change of coating e.g. change of additives in an insulation.	B	A: Risk assessment on application level, if interaction with other material expected.	Parameter analyse only necessary if an anticipated impact on electrical performance.
PAS-PTC-MA-05	Change of material composition - Lead material / Termination	P	P	Change of lead (finish) material, termination material or attachment material	e.g. change from SnPb to pure Sn	B	Risk assessment needed to evaluate compatibility of soldering process.	
PAS-PTC-MA-06	Change of supplier of material	-	P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C		Assumption material specification remains unchanged. Otherwise see change of material.
DESIGN								
PAS-PTC-DE-01	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead Diameter	I	P	Change of lead diameter	e.g. change lead diameter from 0.5 to 0.4 mm	B		
PAS-PTC-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure - Termination Area	I	P	Change of termination area	e.g. change of termination layer thickness e.g. change in termination dimensions	B		SMD components only!
PAS-PTC-DE-03	Changes of termination, surface finish, shape, color, appearance or dimension structure - Internal Connection	I	P	Change of inner connection	e.g. change from soldered connection to welded connection	C		
PAS-PTC-DE-04	Changes of termination, surface finish, shape, color, appearance or dimension structure - Appearance	I	P	Change of appearance. Note: Marking on device is defined as separate change (PAS-PTC-PV-02).	e.g. change or adding of colour on component Mainly in combination with other changes!	B		
PAS-PTC-DE-05	Change of inner construction - Electrode	-	P	Change of electrode layer thickness or geometry.	e.g. change of electrode design	C		
PAS-PTC-DE-06	Change of inner construction - Layer Thickness	-	P	Change of ceramic layer thickness. For multi-layer technology only.	e.g. change from 1.5µm into 1.0µm	C		
PAS-PTC-DE-07	Changes of inner construction - Number of Layers	-	P	Change of number of ceramic or electrode layers. For multi-layer technology only. Always in combination with PAS-PTC-DE-06.	see also layer thickness	C		
PROCESS								
PAS-PTC-PR-01	Changes in process technology or manufacturing methods - Lamination	-	P	Change of lamination / press technique technology	e.g. stamp press to isostatic press.	C		
PAS-PTC-PR-02	Changes in process technology or manufacturing methods - Firing	-	P	Change of firing / sintering profile	e.g. temperature and / or time and / or atmosphere. e.g. from tunnel to batch kiln.	C		
PAS-PTC-PR-03	Changes in process technology or manufacturing methods - Dicing	-	P	Change of dicing / slicing	e.g. change from cutting to sawing	C		
PAS-PTC-PR-04	Changes in process technology or manufacturing methods - Termination	-	P	Change for termination preparation like plating or apply of termination base layer.	e.g. change in plating technology (final termination) e.g. change from dip in paste to plating (apply)	B		
PAS-PTC-PR-05	Changes in process technology or manufacturing methods - Electrode apply	-	P	Change of electrode apply. For multi layer technology only.	e.g. change of inner electrode lay down method.	C		
PAS-PTC-PR-06	Changes in process technology or manufacturing methods - Assembly	-	P	Change in assembly process for leaded or encapsulated devices.	e.g. soldering method for lead attach to element or coating / encapsulation process	B		
PAS-PTC-PR-07	Process integrity: tuning within specification	-	P	Variation within process specification.	e.g. process control	C		
PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS								
PAS-PTC-PN-01	Packing / shipping specification change (loosening of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B		
PAS-PTC-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B		
PAS-PTC-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier (tray, reel)	e.g. change by material e.g. change by geometry.	B		
PACKING / SHIPPING - VISUAL INSPECTION								
PAS-PTC-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(I) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	B		
PAS-PTC-PV-02	Change of product marking	I	P	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B		
PAS-PTC-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	-		
LOGISTICS / CAPACITY / TESTING - EQUIPEMMENT								
PAS-PTC-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes effecting the product not covered by the table require also a PCN.	e.g. change from wet to dry technology.	C		Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-PTC-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	C		Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-PTC-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C		Gage R&R / delta correlation
LOGISTICS / CAPACITY / TESTING - PROCESS FLOW								
PAS-PTC-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one plantsite is not affected.	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B		Characterisation depends on impact of production flow.
PAS-PTC-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes.	C		
LOGISTICS / CAPACITY / TESTING - G-GATE								
PAS-PTC-QG-01	Change of test coverage used by the supplier to ensure date sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	C		Characterisation depends on impact of test coverage. R (relach. func.): test coverage. R (reliability): only for change in burn in process.

ID	Description			Notes	Example	Class	Risk assessment note	Remarks
Any								
PAS-VDR-AN-01	Any change with impact on special customer characteristics/contractual agreements	P	P		Not relevant for technical evaluation.	-		
PAS-VDR-AN-02	Any change with impact on processability/manufacturability at customer, which is not covered in the matrix below.	P	P		Technical interface means component terminals. See processability on board level.	B		
DATASHEET								
PAS-VDR-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and / or AC/DC specification	P	P	Change of application relevant information. Not included: Editorial changes.	e.g. tighten of electrical parameter distribution	A	Risk assessment depending on change for each application.	
PAS-VDR-DS-02	Correction of data sheet	I	P	No technical change of the product, only correction in description (wording, drawing, ...). (I): In case of editorial changes. (P): In case of impact on product integrity.	e.g. data sheet correction because of new information about component behavior	A		
PAS-VDR-DS-03	Specification of additional parameters	I	P	Description of a new not previously covered parameter. No technical change of the product. (I): no influence (P): Risk assessment depending on change for each application to provide evidence of additional parameter (stat. evaluation)	e.g. adding new (tested) parameter.	A		
MATERIAL								
PAS-VDR-MA-01	Change of material composition - Ceramic Binder	P	P	Change of Binder Material to bind ceramics.		C		
PAS-VDR-MA-02	Change of material composition - Ceramic	P	P		e.g. changes in additives amount	C		
PAS-VDR-MA-03	Change of material composition - Electrode	P	P	Change of inner electrode material. Valid in case of multilayer structures only.	e.g. change from AgPt material to AgPd material	C		
PAS-VDR-MA-04	Change of material composition - Encapsulation	P	P	Change of encapsulation material.	e.g. change of coating e.g. change of additives in an insulation.	B	A: Risk assessment on application level, if interaction with other material expected.	
PAS-VDR-MA-05	Change of material composition - Lead material / Termination	P	P	Change of lead (finish) material, termination material or attachment material	e.g. change from SnPb to pure Sn	B	Risk assessment needed to evaluate compatibility of soldering process.	
PAS-VDR-MA-06	Change of supplier of material	-	P	Change to a new or additional material supplier at component manufacturer.	e.g. for 2nd source purpose	C		Assumption material specification remains unchanged. Otherwise see change of material.
DESIGN								
PAS-VDR-DE-01	Changes of termination, surface finish, shape, color, appearance or dimension structure - Lead Diameter	I	P	Change of lead diameter	e.g. change lead diameter from 0.8 to 0.6 mm	B		
PAS-VDR-DE-02	Changes of termination, surface finish, shape, color, appearance or dimension structure - Termination Area	I	P	Change of termination area	e.g. change of termination layer thickness e.g. change in termination dimensions	B		SMD components only!
PAS-VDR-DE-03	Changes of termination, surface finish, shape, color, appearance or dimension structure - Internal Connection	I	P	Change of inner connection	e.g. change from soldered connection to welded connection	C		

Code	Description	Col1	Col2	Change detail	Example	Class	Notes
PAS-VDR-DE-04	Changes of termination, surface finish, shape, color, appearance or dimension structure – Appearance	I	P	Change of appearance. Note: Marking on device is defined as separate change (PAS-VDR-PV-02).	e.g. change or adding of colour on component. Mainly in combination with other changes!	B	
PAS-VDR-DE-05	Change of inner construction - Electrode	-	P	Change of electrode layer thickness or geometry.	e.g. change of electrode design	C	
PAS-VDR-DE-06	Change of inner construction - Layer Thickness	-	P	Change of ceramic layer thickness. For multi-layer technology only.	e.g. change from 1.5μm into 1.0μm	C	
PAS-VDR-DE-07	Change of inner construction - Number of Layers	-	P	Change of number of ceramic or electrode layers. For multi-layer technology only. Always in combination with PAS-VDR-DE-06.	see also layer thickness	C	
PAS-VDR-DE-08	Change of inner construction - Grain size	-	P	Change of grain size. Grain size is a result of process and / or material change.	e.g. change of grain size.	C	
PAS-VDR-DE-09	Change of inner construction - Grain boundary size	-	P	Change of grain boundary size. Grain boundary size is a result of process and / or material change.	e.g. change of grain boundary size.	C	
PROCESS							
PAS-VDR-PR-01	Change in process technology or manufacturing methods - Lamination	-	P	Change of lamination / press technique method.	e.g. pressures or temperature	C	
PAS-VDR-PR-02	Change in process technology or manufacturing methods - Firing	-	P	Change of firing / sintering profile.	e.g. temperature and / or time and / or atmosphere. e.g. from tunnel to batch kiln.	C	
PAS-VDR-PR-03	Change in process technology or manufacturing methods - Dicing	-	P	Change of dicing	e.g. change from cutting to sawing	C	
PAS-VDR-PR-04	Change in process technology or manufacturing methods - Termination	-	P	Change for termination preparation like plating or apply of termination base layer.	e.g. change in plating technology (final termination) e.g. change from dip in paste to plating (apply)	B	
PAS-VDR-PR-05	Change in process technology or manufacturing methods - Electrode apply	-	P	Change of electrode apply. For multi layer technology only.	e.g. change of inner electrode lay down method	C	
PAS-VDR-PR-06	Change in process technology or manufacturing methods - Assembly	-	P	Change in assembly process for leaded or encapsulated devices.	e.g. soldering method for lead attach to element or coating / encapsulation process	B	
PAS-VDR-PR-07	Process integrity: tuning within specification	-	P	Variation within process specification.	e.g. process control	C	
PACKING / SHIPPING - NEW MATERIAL, CRITICAL DIMENSIONS							
PAS-VDR-PN-01	Packing / shipping specification change (loosening of tolerances)	P	P	Change of packing specification.	e.g. number of pieces on reel.	B	
PAS-VDR-PN-02	Dry pack requirements change	P	P	Change of drypack requirements.	e.g. change of MSL e.g. change in dry pack assurance (HIC, MBB)	B	
PAS-VDR-PN-03	Change of carrier (tray, reel)	P	P	Change of carrier	e.g. change by material e.g. change by geometry.	B	
PACKING / SHIPPING - VISUAL INSPECTION							
PAS-VDR-PV-01	Change of labelling	I	P	Change of labelling, also on reel.	(I) e.g. additional information (RoHS stamp) (P) e.g. change of customer specific information	B	
PAS-VDR-PV-02	Change of product marking	I	P	Marking on device.	e.g. change of content of marking e.g. change of method of marking e.g. change of appearance of marking	B	
PAS-VDR-PV-03	Change of packing/shipping specification	P	P	Change in packing specification which does not described a change of dimensions or material of the packing.	e.g. change of documentation in packing specification	*	
LOGISTICS / CAPACITY / TESTING - EQUIPEMENT							
PAS-VDR-EQ-01	Production from a new equipment/tool which uses a different technology or which due to its unique form or function can be expected to influence the integrity of the final product	P	P	Change in process technique which is not already covered above. Note: Changes affecting the product not covered by the table require also a PCN.	e.g. change from wet to dry technology.	C	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-VDR-EQ-02	Production from a new equipment/tool which use the same basic technology (replacement equipment or extension of existing equipment pool)	-	P	PCN required for dedicated equipment for sensitive component production.	e.g. elimination of manual handling processes	C	Test effort depends on final risk assessment. Performance test according to affected process change.
PAS-VDR-EQ-03	Change in final test equipment type that uses a different technology	P	P	Change of final test equipment which use different technology. PCN required for dedicated equipment for sensitive parameters.	e.g. change of tester platform	C	Gage R&R / delta correlation
LOGISTICS / CAPACITY / TESTING - PROCESS FLOW							
PAS-VDR-PF-01	Manufacturing site transfer or movement of a part of production process to a different location/site	P	P	Change of manufacturing site. Note: Reorganization inside one plantsite is not affected!	Movement or transfer of manufacturing site or process step(s) to a different location/site.	B	
PAS-VDR-PF-02	Elimination or addition of a manufacturing process step	-	P	Change of manufacturing process sequence.	e.g. washing / cleaning process e.g. change of order of processes	C	Characterisation depends on impact of production flow.
LOGISTICS / CAPACITY / TESTING - Q-GATE							
PAS-VDR-QG-01	Change of test coverage used by the supplier to ensure data sheet compliance (e.g., elimination/addition of electrical measurement/test flow block, relaxation/enhancement of monitoring procedure or sampling)	-	P	Change of test coverage.	e.g. change from 100% to sample inspection e.g. test flow block, reduction from three to two temperature measurements e.g. change in burn in/run in process.	C	R (elect. funct.): test coverage. R (reliability) only for change in burn in process.

Tests, which should be considered for the appropriate process change.

Tests, which should be considered for the appropriate process change after selection of condition table.

Suppliers performed tests (mark with an 'X' for done or 'G' for generic)

Reason for exception of tests and/or usage of generic data:

--	Not required
I	Information Note required
P	PCN required

A letter or "•" indicates that performance of that stress test should be considered for the appropriate process change.

CONDITIONS	No
A	Termination equipment only
C	Ceramics only
B	Comparative data (unchanged vs. changed) required
E	Capacitive trimmers only
F	Film products only
N	Networks only
R	Resistors only
S	SMD components only
W	Wirewound products only
Y	Component not hermetically sealed
Note 1:	For parts marked with ink only. Laser and stamp marked parts shall be exempt.

=> Please mark 'NO' with 'x', default is 'YES'

Device evaluation

MATERIAL PERFORMANCE TEST RESULTS (on the basis of IEC 60810)

Mark change with an "x"

ID	Type of change	Assessment of Impact on Supply Chain regarding following aspects — contractual agreements — technical interface of processability/manufacturability of customer — form, fit, function, quality performance, reliability	Remaining risks on Supply Chain? (No / Yes)	Understanding of semiconductors experts	Examples to explain	Evaluation level A / B / C	Further applicable conditions	Remarks
	ANY							
LED-AN-01	Any change with impact on agreed upon contractual agreements	P / P	Not relevant for technical evaluation.				
LED-AN-02	Any change with impact on technical interface or processability/manufacturability of customer, which is not covered in the matrix below	P / P	See processability on board level technical interface means component terminals.		B	Check if LED-DS-01 is affected. Processability should be assessed.	
	DATA SHEET							
LED-DS-01	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or Pulse/DC specification	P / P	Change of application relevant information (e.g. maximum pulse current). Not included: Editorial changes.		A		
LED-DS-02	Correction of data sheet	I / P	Data sheet (editorial changes) has to check if application affected. I: in case of editorial changes P,I: case of impact on product integrity	e.g. change of ESD level	A		
LED-DS-03	Specification of additional parameters	I / P	Definition of an additional parameter which was not specified before ...	e.g. adding new tested parameter	C		Formalism since this is not a product change, any additional information Classification: C
	DESIGN							
LED-DE-01	Design changes in epitaxy	P / P	Any device relevant changes in design / layout of epitaxial layers. Not included: Changes within design rules and design specification without affecting specified functions, parameters and reliability.	e.g. change from Double-hetero to Quantum wells e.g. change of barrier thickness	C	A: change from Double-hetero to Quantum well → spectrum is affected	
LED-DE-02	Design changes in routing/layout.	P / P	Any change in chip design / layout. Not included: Changes within design rules and design specification without affecting specified functions, parameters and reliability.	e.g. change in layout of current spreader; thickness of current spreader. e.g. reduction of bond pad size	C	A: change of layout of current spreader → radiation pattern changes	TR might be considered for complex die bond technologies
LED-DE-03	Die shrink	P / P	Shrink of active area. Not included: scaling street/kerf/scribe line	Typical shrink of die.	A		
LED-DE-04	LED package (except leadframe)	P / P	any change in housing thickness any change in form or dimensions	e.g. change of dimensions e.g. change of x, y, or z dimension of the package	B	Check if LED-DS-02 is affected which leads to a change of the elctrooptic parameters or distributions.	
LED-DE-05	Design of leadframe	P / P	any change of leadframe / carrier dimensions any change of outer dimensions	e.g. change in leadframe / carrier dimensions in x,y, or z direction. e.g. change inner design of the leadframe not affecting the e/o performance & reliability of the device	B	Check if LED-DS-02 is affected which leads to a change of the elctrooptic parameters or distributions.	
	PROCESS - WAFER PRODUCTION							
LED-PW-01	New / change of wafer substrate or carrier material	P / P	New wafer substrate material.	e.g. different wafer material to currently released material (change from Sapphire to Silicon)	C	Check if LED-DS-02 is affected which leads to a change of the elctrooptic parameters or distributions.	
LED-PW-02	Wafer diameter	P / P	change of wafer diameter resulting in equipment and process changes	e.g. 4" to 6"	C	In case other type of changes are affected i.e equipment/process technology - they need to be identified in addition	
LED-PW-03	New/final wafer thickness	P / P	Change in final wafer thickness.	e.g. change in final chip/die thickness	C	Check if LED-DS-02 is affected which leads to a change of the elctrooptic parameters or distributions.	
LED-PW-04	Change of electrically active doping/implantation element	P / P	Change in electrically active doping / implantation element resulting in a new technology.	e.g. change from Be to C as dopant	C		
LED-PW-05	Change of stacking	P / P	change in layer sequence or thickness	e.g. change of isolation layer thickness between n- and p-material	A	customer application needs to be checked due to potential system voltage differences	
LED-PW-06	New / change of metallization (specifically chip frontside)	P / P	Change in metallization of bondpads, material, layer thickness	e.g. change in bond pad metallization thickness	C		
LED-PW-07	New / change of metallization (specifically chip backside)	P / P	Change of bottom layer of die (between die and leadframe/carrier). Change in process, material, or dimensions necessary.	e.g. change from Au to Au/Ge	C	A: customer application needs to be checked due to potential system voltage differences	
LED-PW-08	Change in process technique (e.g. significant process changes like lithography, etch, oxide deposition, die back surface preparation/background, ...)	— / P	Change for back to dry etching, change from horizontal to vertical oven for oxidation, change from contact litho into stepper litho, ...	e.g. change from wet etch to dry etch e.g. change from laser cutting (sawing) to plasma cutting (sawing) e.g. change from contact litho to stepper litho	C	B: change from CVD dep to sputter dep for backside/frontside metallization. In case of new equipment please check if LED-PA-14 is also affected.	
LED-PW-09	Process Integrity: Tuning within specification	— / P	Variation within process specification	e.g. process control	C		
LED-PW-10	Change of material supplier with no impact on agreed specifications	— / P	Change of supplier for chemicals needed for wafer production.	e.g. Change of wafer supplier.	C		Qualification effort depends on type of change
LED-PW-11	Change of specified wafer process sequence (deletion and/or additional process step)	— / P	Any change which is not covered by another type of change, then is to be assessed.	e.g. additional cleaning process in wafer production	C		Qualification effort depends on type of change PPAP has to be updated
LED-PW-12	Change in die coating or passivation	P / P	Change in material, thickness, and process for coating and passivation	e.g. change from SiO2 to SiN3	C	A or B: Impact on other type of changes	
LED-PW-13	New wafer production location or transfer of wafer production to a different not previously released location/site/subcontractor	P / P	New wafer production location or transfer of wafer production with possible additional changes.		C	A or B: Impact on other type of changes described under PROCESS - WAFER PRODUCTION and EQUIPMENT categories of this DoCaMa	
	BARE DIE DELIVERIES							
LED-BD-01	New / change of front side metallization	P / P	Change in bondpads, material, pad pitch, surface changes, layer thickness.	e.g. change from Au to Au alloy e.g. change in over pad metalization	B		
LED-BD-02	New / change of backside metallization	P / P	Change of bottom layer of die (between die and leadframe/carrier). Change in process, material, or dimensions	e.g. change from Au to Au alloy	B	Check if LED-DS-02 is affected which leads to a change of the elctrooptic parameters or distributions.	customer application needs to be checked due to potential system voltage differences
LED-BD-03	Change of wafer setup or number of dies on wafer.	I / P	Changes in number of chips P: change in distance between chips and form of wafer	e.g. information change for pick & place machine.	B		
LED-BD-04	New/final wafer thickness	P / P	Changes in final Chip height (including carrier), very rare and usually combined with a material change (change of carrier material)	e.g. change on converter thickness	B	Check if LED-DS-01 is also affected.	
LED-BD-05	Change in die coating or passivation	P / P	Change in material, thickness, and process for coating and passivation	e.g. change from SiO2 to SiN3	B	Check if LED-DS-01 is also affected.	
	PROCESS - ASSEMBLY							
LED-PA-01	New leadframe/carrier base material	P / P	New leadframe/carrier material (new in composition)	e.g. change from copper alloy to bare copper	B	Check if LED-DS-02 is affected which leads to a change of the elctrooptic parameters or distributions.	Explanation should be provided in case H2S test is not applicable
LED-PA-02	Change of leadframe/carrier finishing material (internal)	P / P	Change of surface material of die attach pad and second bond area (e.g. influence in adhesion to mold compound, wedge bond reliability)	e.g. change from Ag flash to NiPd protection layer e.g. change from Ag spot to Au spot	A		NiES test should be considered for automotive external applications. explanation should be provided in case H2S test is not applicable
LED-PA-03	Change of lead and heat slug plating material/plating thickness (external)	P / P	Change in material and process technique for final pin termination (e.g. pure tin). Herein package, processability and reliability on board level can be verified by generic data. Classification depends on impact of change.	e.g. change to heat slug stack e.g. change from Sn into NiPd/Au, e.g. change of layer thickness	B		Explanation should be provided in case H2S test is not applicable
LED-PA-04	Bump Material / Metall System (internal)	P / P	Stack die or die to substrate	e.g. change to Pb-free material	A		
LED-PA-05	Die attach material	P / P	Change of die attach material (e.g. soft solder, epoxy, etc). Thermal management must be respected.	e.g. change of Ag glue to Au glue;	B		
LED-PA-06	Material, wire diameter, change in process technique	P / P	Material, wire diameter, change in process technique	e.g. change from 30μ to 20μ	A		Wire audit for material change with impact on bond process (e.g. from Au to Cu) recommended.
LED-PA-07	Change in material for sub-components (excluding LED chip & LED package related items) with impact on agreed specifications	P / P	Change of sub-component supplier using different technology/materials. Note: Jump start test at OEMs might be necessary	e.g. using a different ESD-diode in technology and material then previously	A	Check if LED-DS-01 is also affected.	Qualification effort depends on type of change.
LED-PA-08	Die Overcoat / Underfill	— / P	Supporting layers for complex packages like flip chip. — No change in product integrity P: change can influence the integrity of final product	P: e.g. change of underfill with change of thermal resistance	B	Check if LED-DS-01 is also affected.	
LED-PA-09	Change of mold compound/encapsulation/sealing material	P / P	Change of mold compound, encapsulation, or sealing material might be affected optical function in case of package related effect (e.g. browning). Component assembly and board coating has to be assessed. MSL might be changed.	e.g. PPA mold compound	A	Check if LED-DS-01 is also affected.	
LED-PA-10	Change of conversion material	P / P	Change of material class.	e.g. change from granate to nitrides	C	Check if LED-DS-01 is affected for optical/photometric parameters	
LED-PA-11	Change of direct supplier for converter material	— / P	New supplier with same material specification		C		
LED-PA-12	Change of converter process technology	I / P	Technology for converter production b: no influence on e/o performance of product P: in case of impact on product integrity	e.g. change from volume conversion to layer conversion; e.g. change from stamping to printing of layer	C	Check if any change in electro-optical characteristics results in change of data sheet LED-DS-01	
LED-PA-13	Change of product marking	I / P	Marking on device. P: change in appearance; readability not affected P: change of content or change of appearance of data matrix code	e.g. marking of cathode;	B		
LED-PA-14	Change in process technique (e.g., die attach, bonding, molding, plating, trim and form, ...)	— / P	Any change in assembly process technique	e.g. change die attached from gluing to soldering;	B	A or B: Please check if EQUIPMENT and other type of changes of material (LED-PA-04/05/06/07/08/09/10) are affected	Qualification effort depends on type of change
LED-PA-15	Process Integrity: Tuning within specification	— / P	Variation within process specification	e.g. process control	C		
LED-PA-16	Change of direct material supplier with no impact on specification	— / P	Change of suppliers e.g. for lead frames, wire material, die attach, electronical components ...	Change of suppliers e.g. for lead frames, wire material, ESD-diode ...	C	Assumption then change material specification remains unchanged. Otherwise see change of material.	See change of material.

PROCESS ASSEMBLY (continued)

ID	Description			Detail	Example		Comment	Qualification
LED-PA-17	Change of specified assembly process sequence (additional and/or deletion of process step)	I	P	Addition or deletion of a process step in assembly process sequence with potentially significant impact on the product performance. **I:** no influence on product integrity. **P:** influence on product integrity expected	e.g. additional or deletion plasma cleaning process.	C	Single case assessment necessary to identify possible interactions or risk.	Qualification effort depends on type of change.
LED-PA-18	New assembly location or transfer of assembly to a different not previously released location/site/subcontractor	P	P	New assembly location, assembly transfer or relocation. Transfer of known technology and equipment.	e.g. Dual source strategy	C	**A** or **B:** Impact on other type of changes described under **PROCESS ASSEMBLY** and **EQUIPMENT**	Qualification effort depends on type of change.

PACKING/SHIPPING

ID	Description			Detail	Example		Comment	Qualification
LED-PS-01	Inner Packing/shipping specification change	P	P	dimension change of direct product packing	e.g. SMT packed in tape changes	B		
LED-PS-02	Outer Packing/shipping specification change	I	P	dimension changes indirect product packing **I:** small changes in dimension or appearance **P:** number of reels in the packing are changing	e.g. pizza box	*		
LED-PS-03	Change of labelling	I	P	Change of labelling also on reel. **I:** additional information no change of previous information **P:** change in content of previous information	(**I:**) e.g. additional information (RoHS stamp) (**P:**) e.g. change of customer specific information	B	Check if **LED-DS-01** is also affected.	
LED-PS-04	Dry pack requirement change	P	P	Change of dry pack requirements (change in MSL)	e.g. change from MSL3 to MSL1	*	Check if **LED-DS-02** is also affected.	

EQUIPMENT

ID	Description			Detail	Example		Comment	Qualification
LED-EQ-01	Production from a new equipment/tool which uses a different basic technology	P	P	Change in process technique which is not already covered above. **Note:** Major changes affecting the product not covered by the table require also a PCN.	e.g. change from single wafer to batch process. e.g. over pad metallization e.g. dambar cutting (mechanical to laser cutting)	B	Check if **LED-DS-01** is also affected. Corrosion stability should be assessed.	Qualification effort depends on type of change.
LED-EQ-02	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	--	P	PCN required for dedicated equipment for sensitive component production.	e.g. change from single site to multi site handler.	C		
LED-EQ-03	Change in final test equipment type that uses a different technology.	I	P	Change of tester platform (e.g. major test program changes, new tester interface, …). **I:** product specification is not affected **P:** product specification is affected	e.g. change in test method from ct to lumen.	B		Gage R&R / data correlation

TEST FLOW

ID	Description			Detail	Example		Comment	Qualification
LED-TF-01	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	P	P	Tester transfer or relocation.	e.g. Dual source strategy	C		Gage R&R / data correlation; additional specification check should be considered for Wafer testing

Q-GATE

ID	Description			Detail	Example		Comment	Qualification
LED-QG-01	Change of the test coverage testing process flow used by the supplier to ensure data sheet compliance (e.g. elimination/addition of electrical measurement/test block; relaxation/enhancement of monitoring procedure or sampling)	--	P	Reduction or additional control steps; test coverage within the process flow	e.g. test flow/block like Final test / final clearance	C		

Tests, which should be considered for the appropriate process change.

Tests, which should be considered for the appropriate process change after selection of condition table.

Suppliers performed tests (mark with an 'X' for done or 'G' for generic)

Reason for exception of tests and/or usage of generic data:

--	Not required.
I	Information Note required.
P	PCN required.

A letter or "●" indicates that the performance of that stress test should be considered for the appropriate process change.

	CONDITIONS	No.
A	Not for Ag plated devices applicable (Ag intended to fail for this test)	
B	Only if Bondarea/Wirebond is changed/affected	
C	Only if dopand/implantation material is changed	
D	Only if Dimensions are changing	
E	Only if min/max Values are changing	
F	Sequence change only	
H	Non Epoxy Coated Devices only	
J	Only for chip technology using wafer bonding	
K	Not for Au plated devices	
L	Only if Leadframe/Substrate Dimensions are changed	
M	Only if metal composition is changed including sequence	
N	Only for glued chips	
O	Only for glued chips	
P	Only if material properties are changed	
Q	Only if glue components are changing	
R	Only if marking technology changes	
S	Only if Floor Life is affected	
T	Only if Board Reliability is affected	
U	Only if underfill is affected	
V	Only for non-hermetic devices	
W	Only if risk of corrosion is increasing	
Y	Only for layer technology	
Z	Only if conversion technology changes	
1	Only if data sheet parameters are affected	
3	Only if outer dimensions are critical	
	=> Please mark 'NO' with 'x', default is 'YES'	